

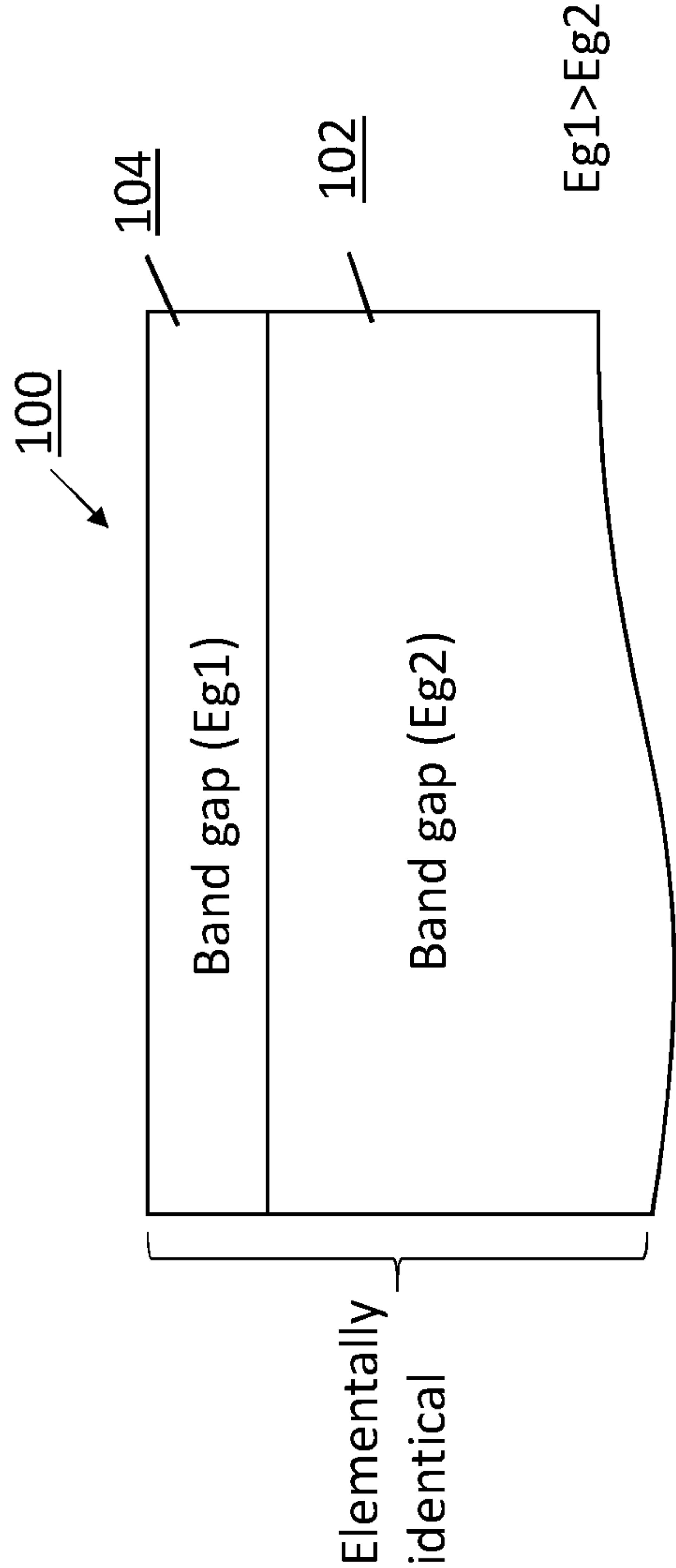


FIG. 1

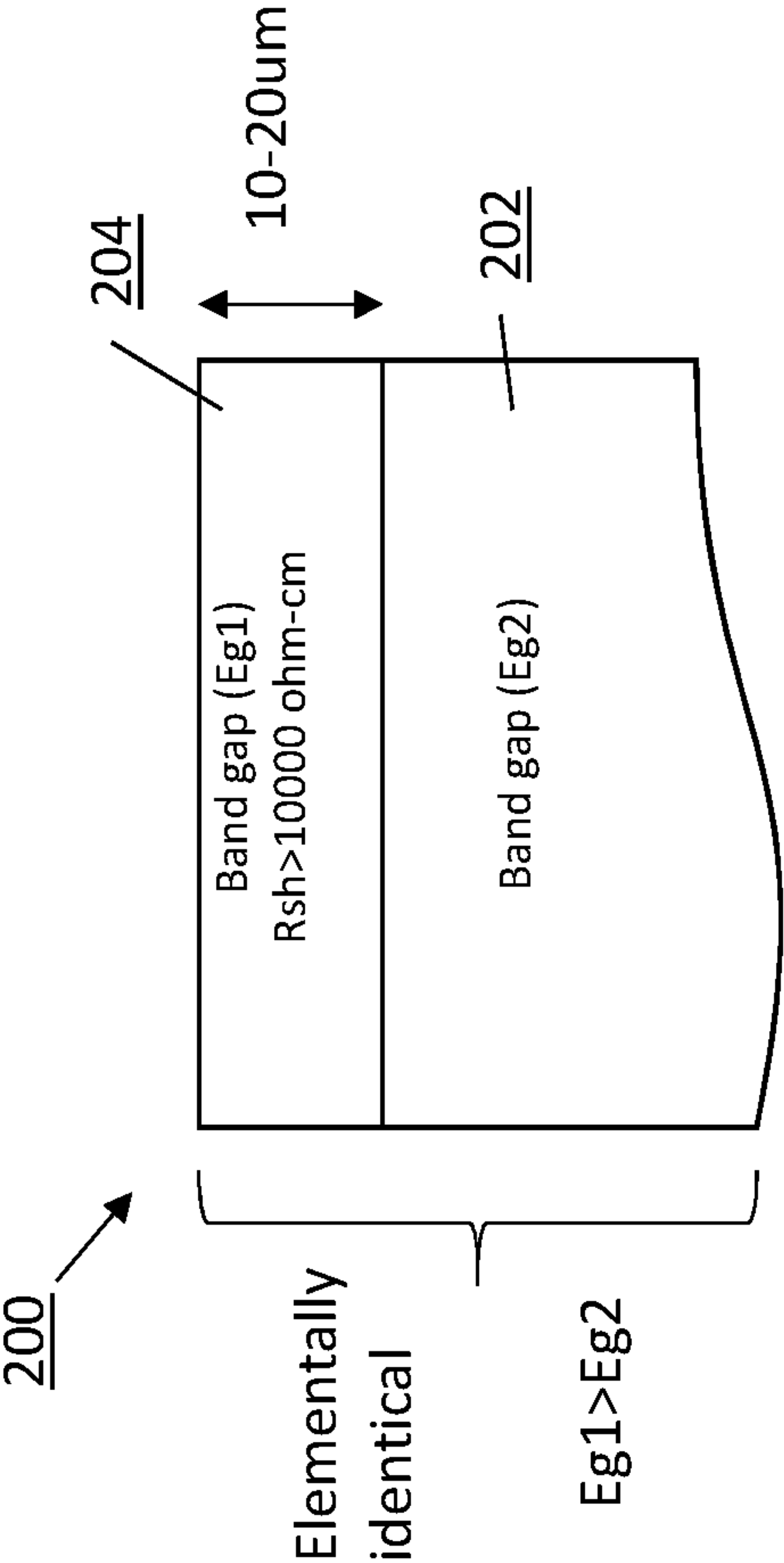


FIG. 2

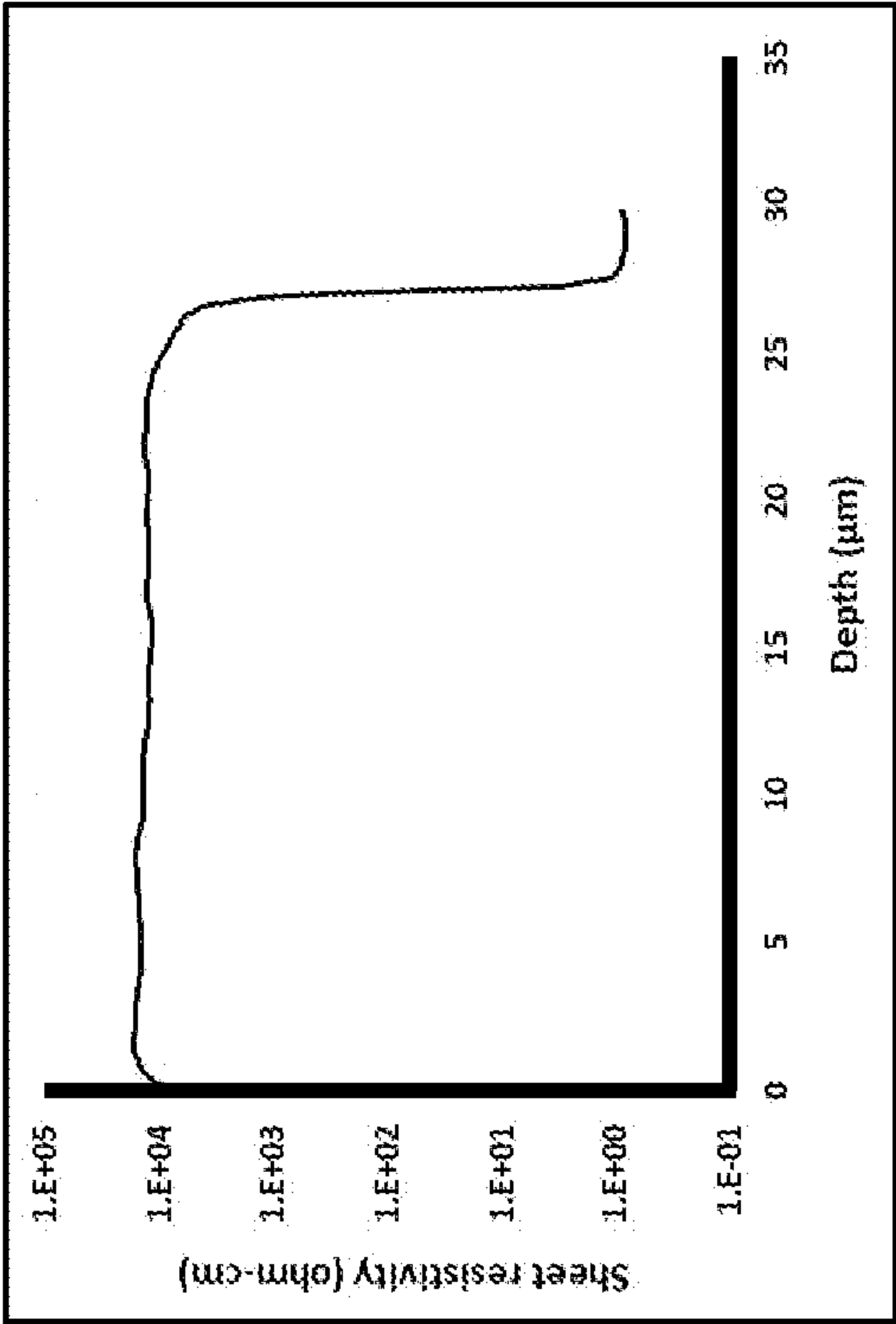
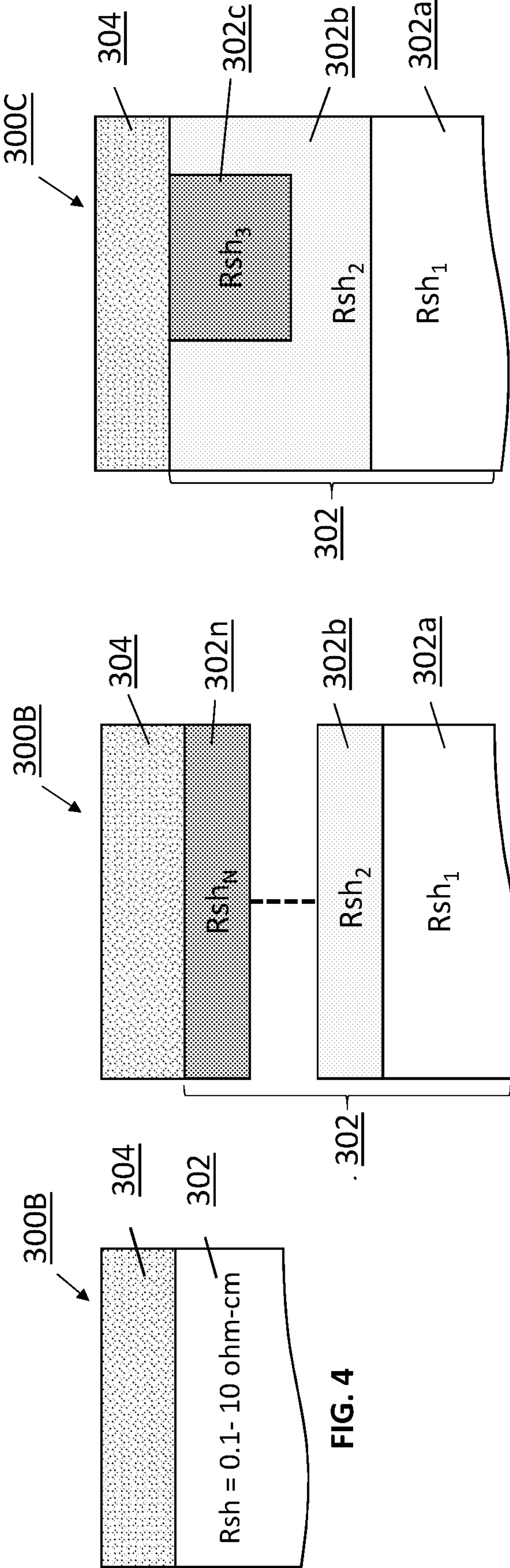


FIG. 3



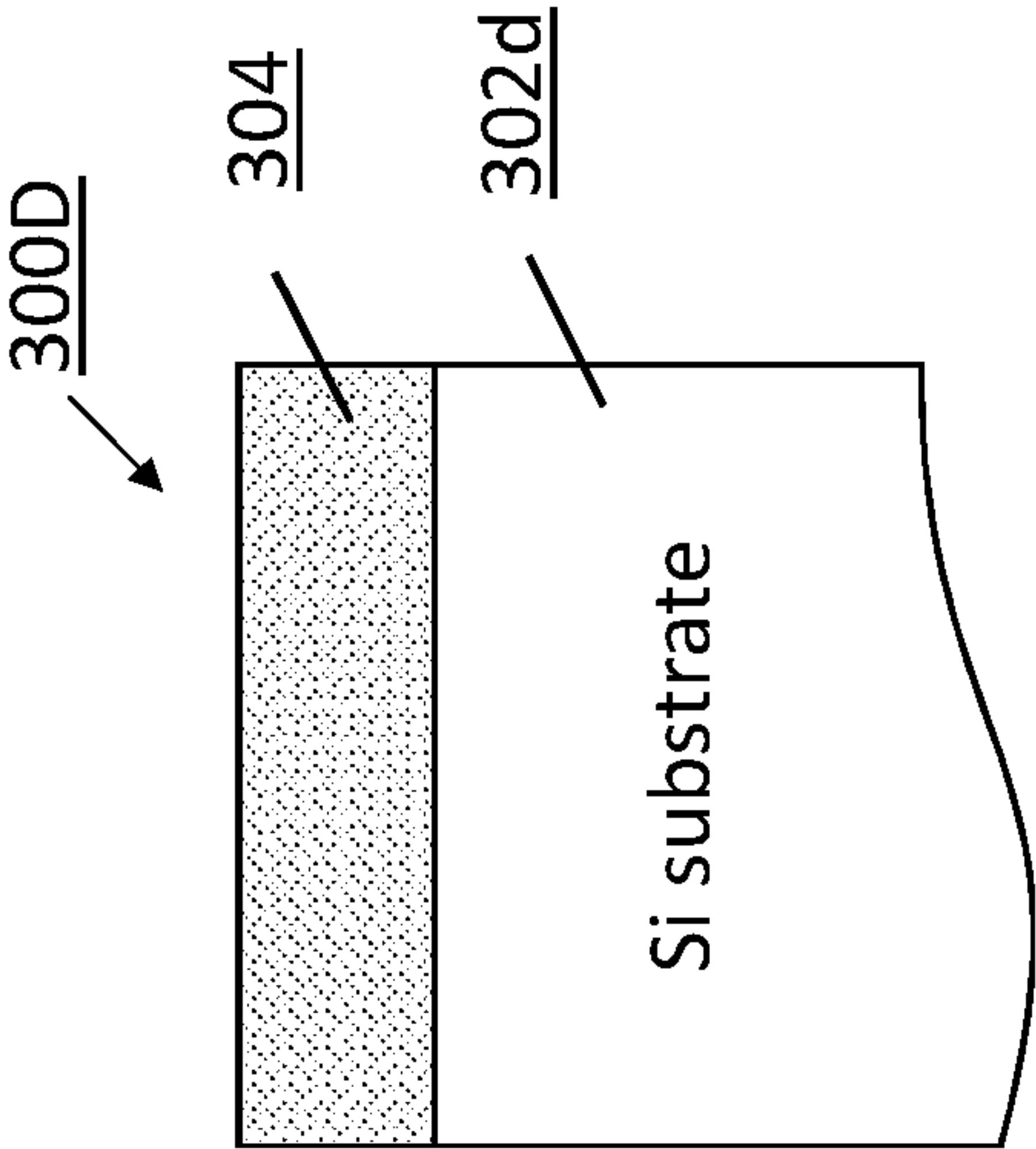


FIG. 7

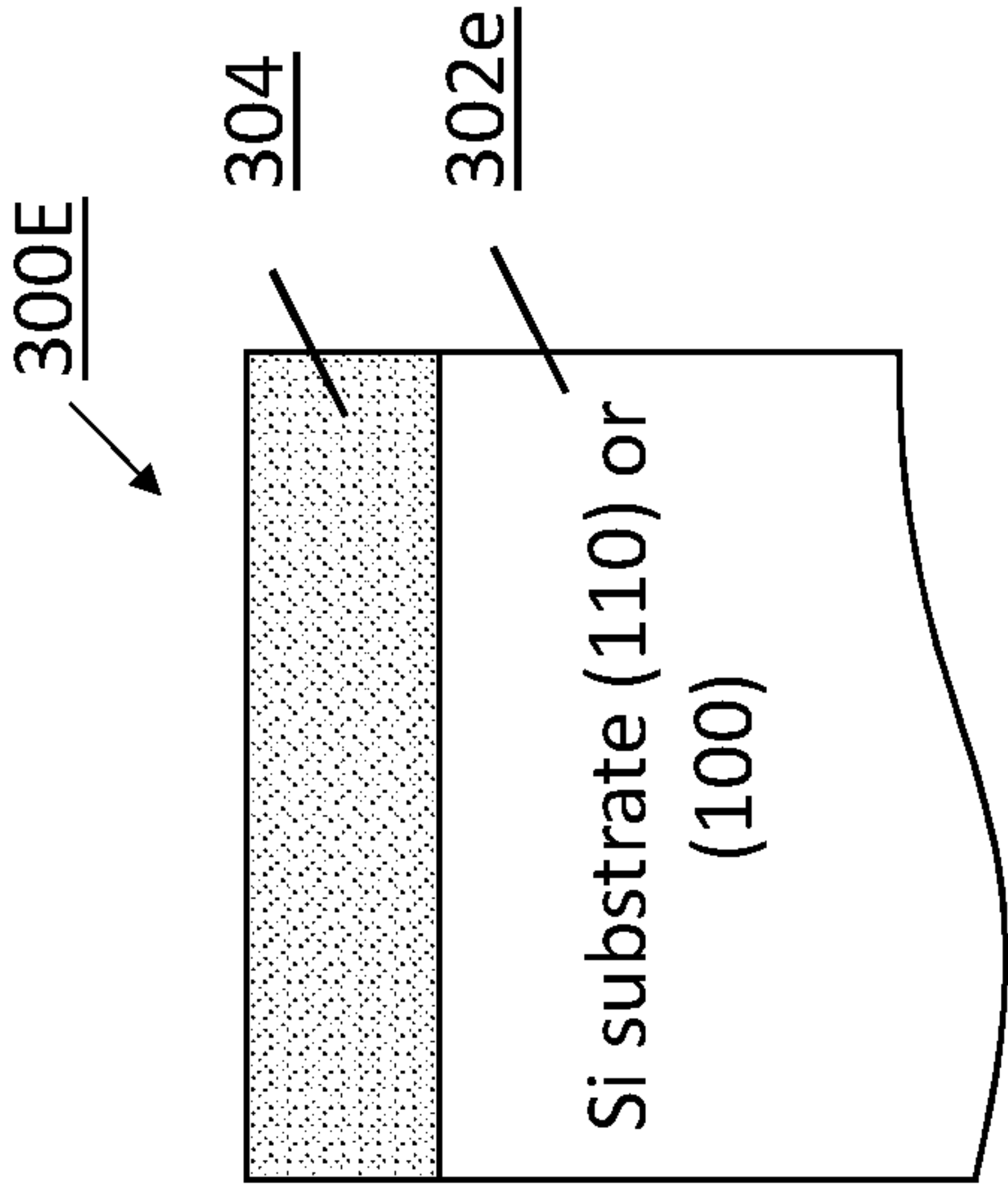


FIG. 8

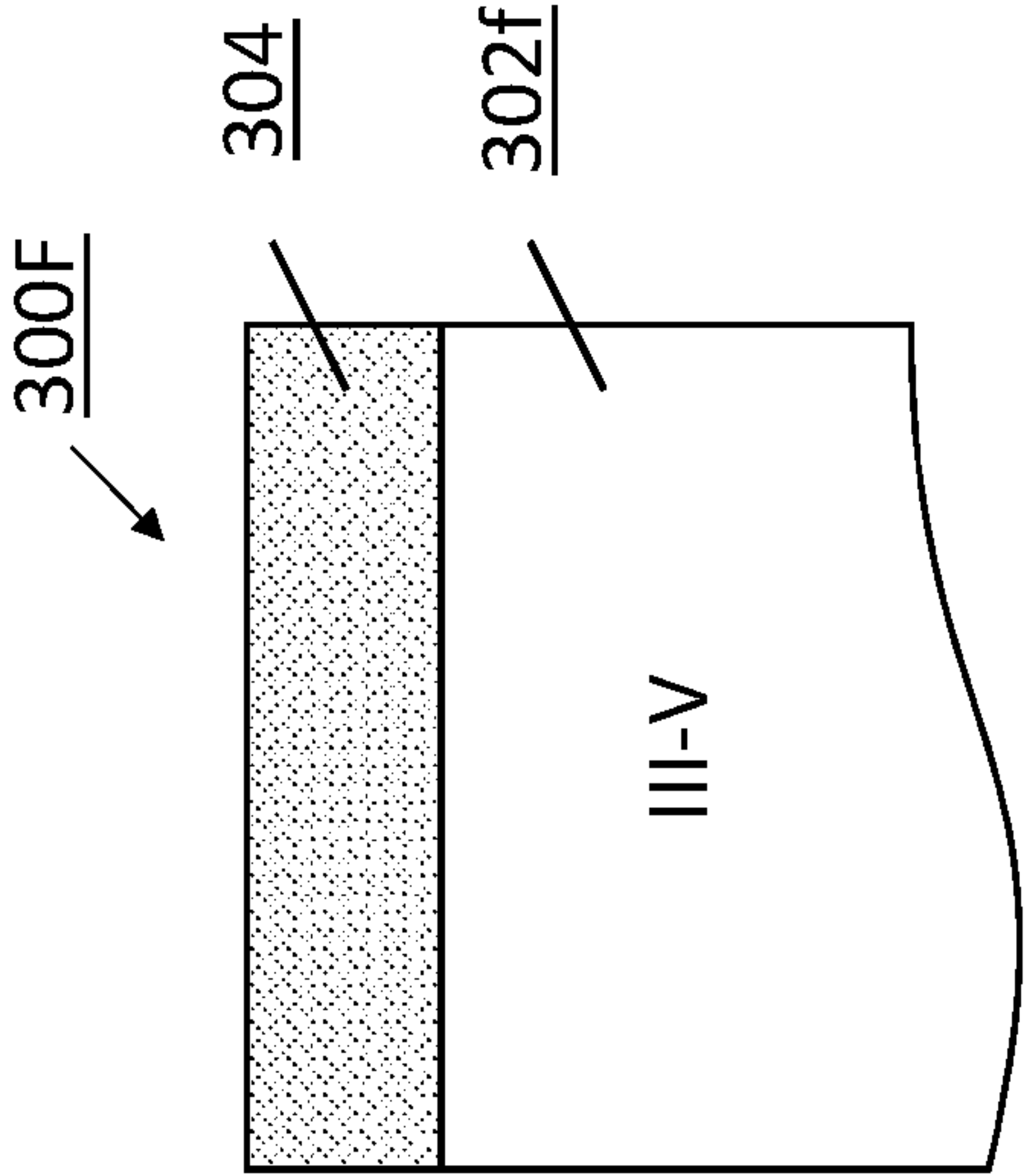
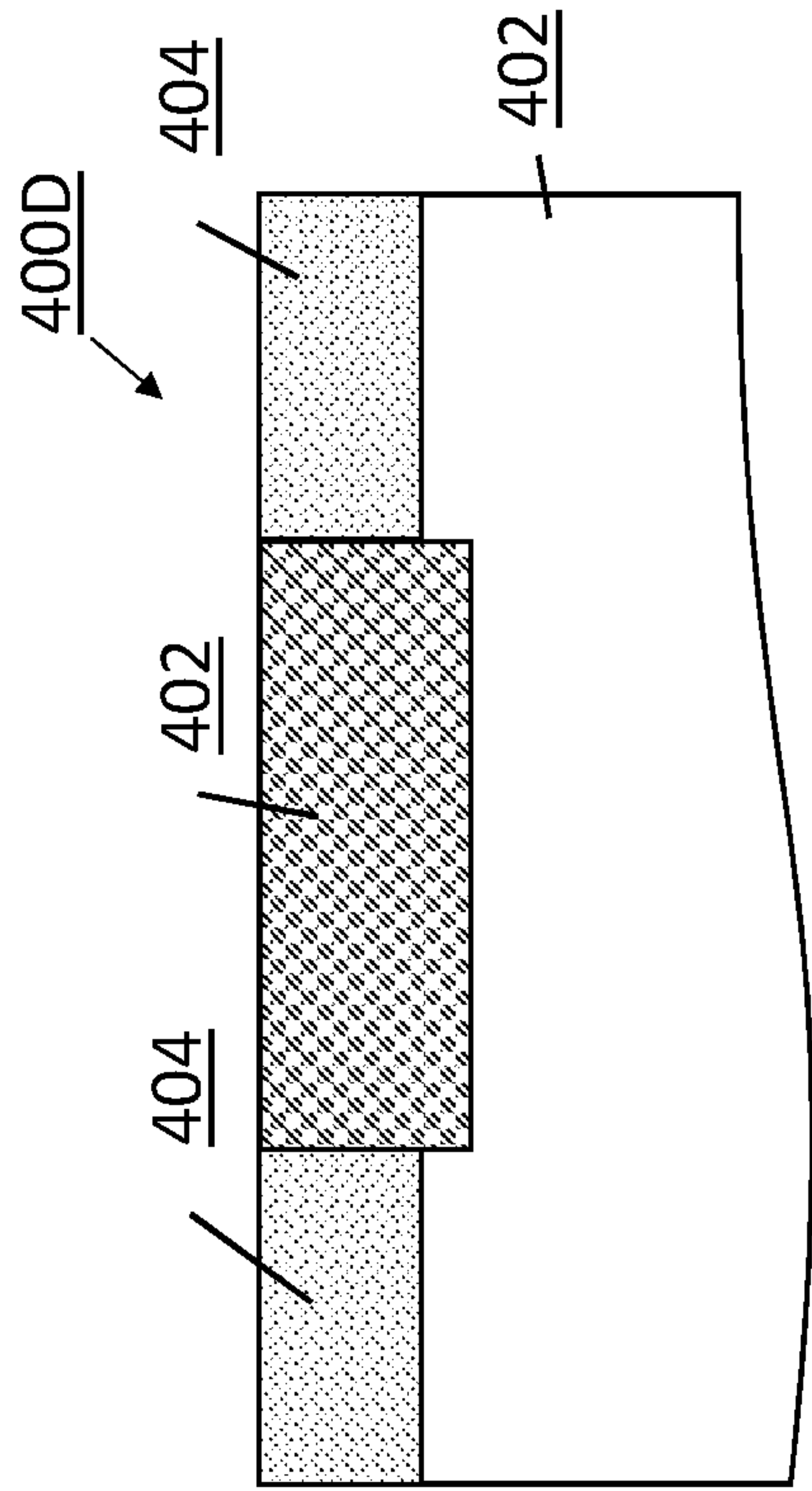
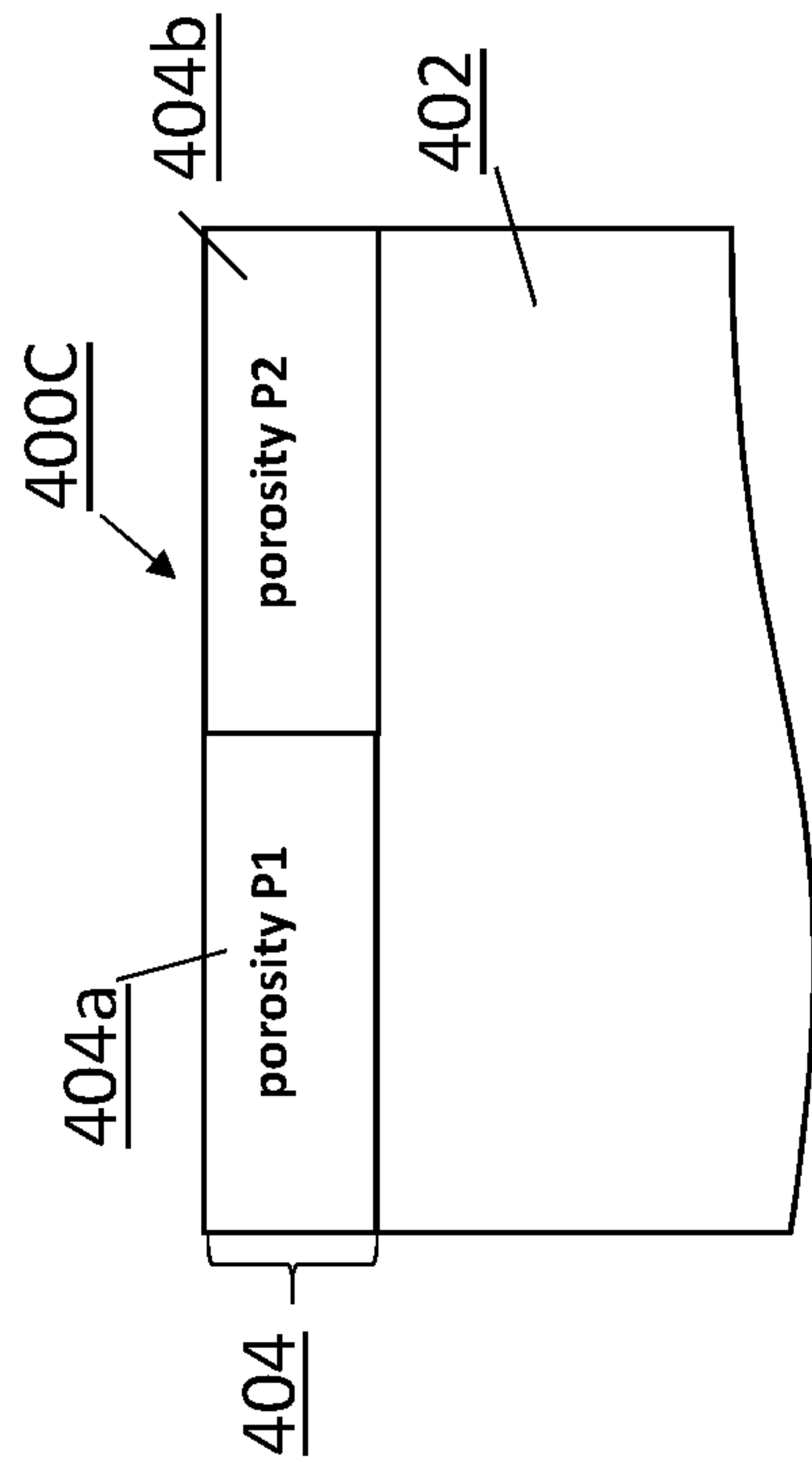
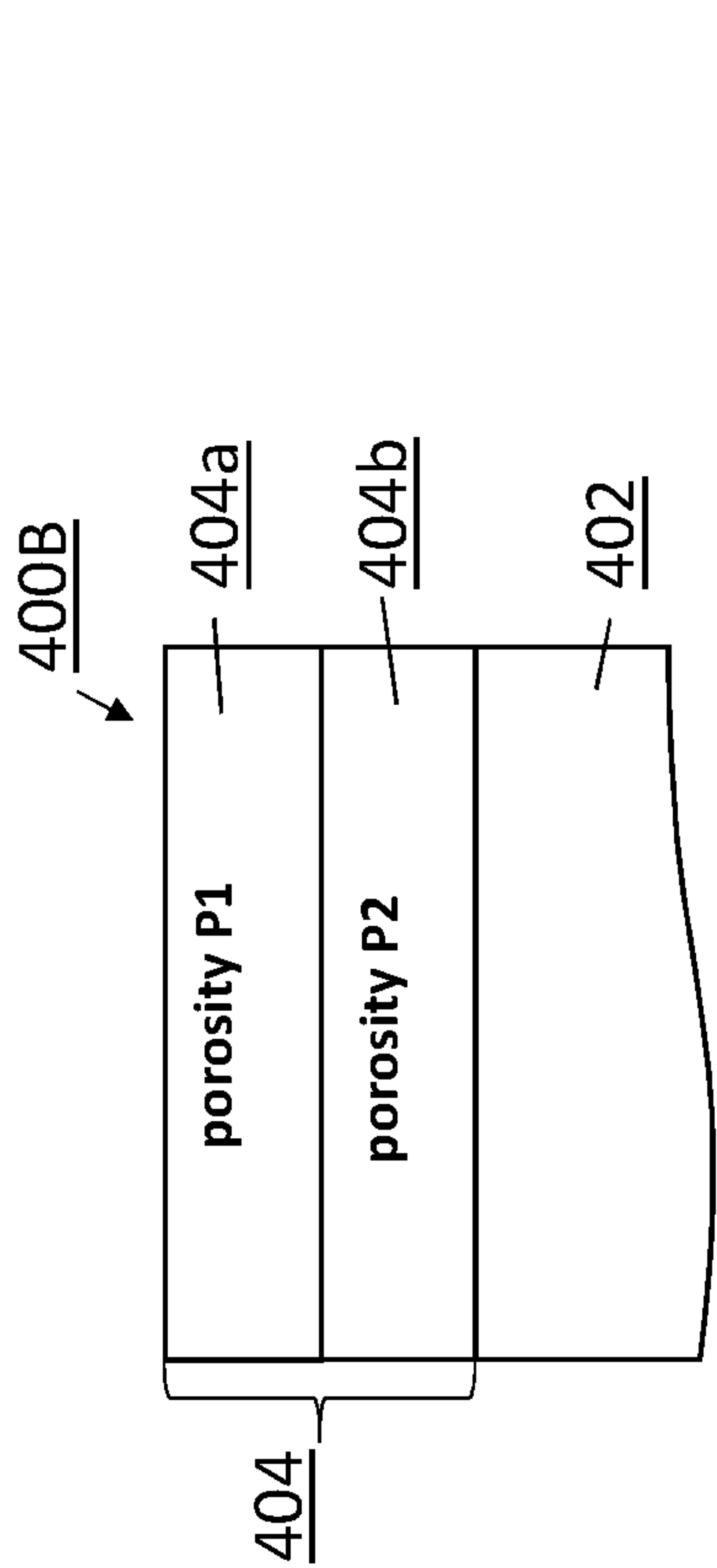
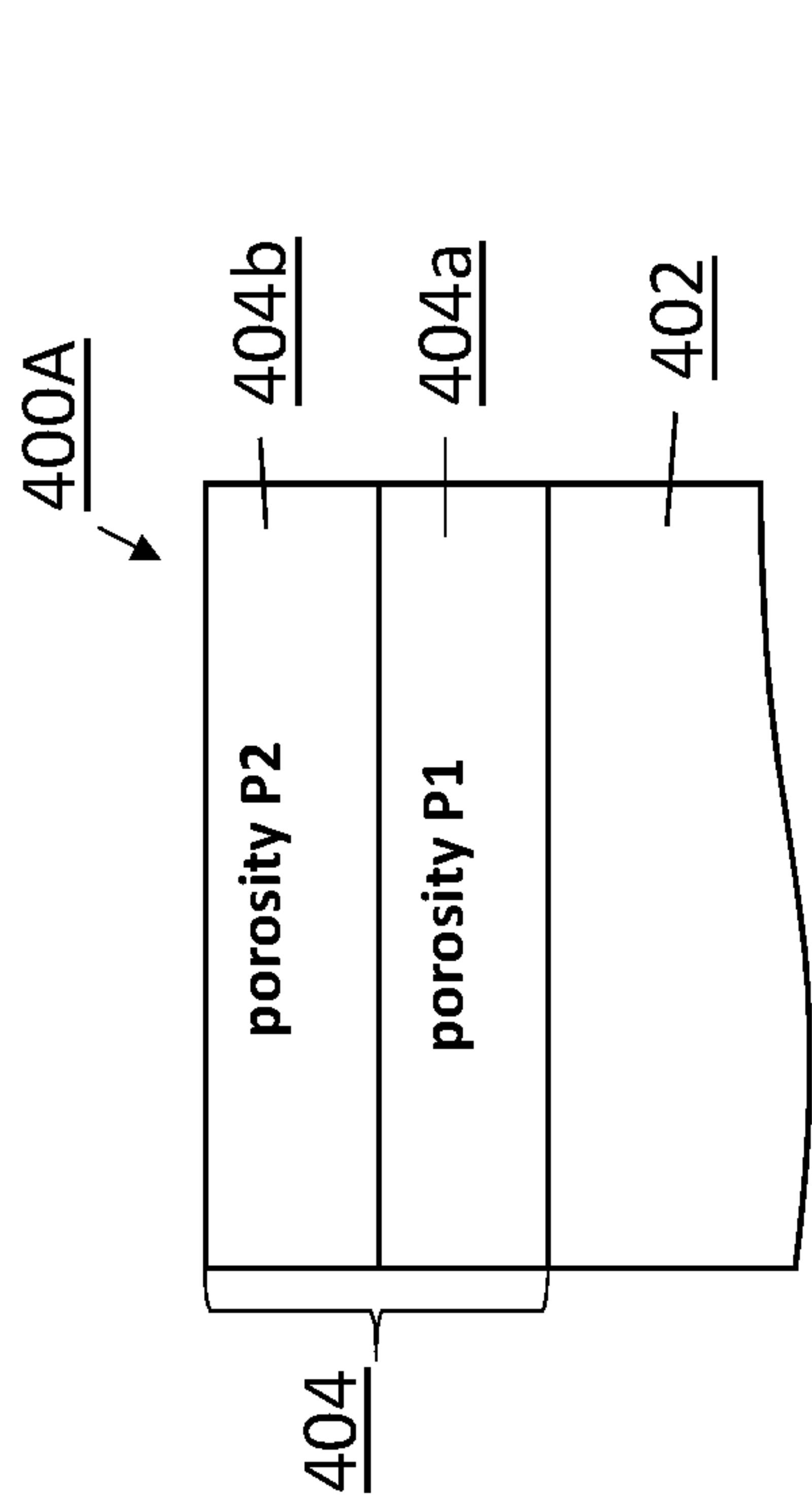


FIG. 9



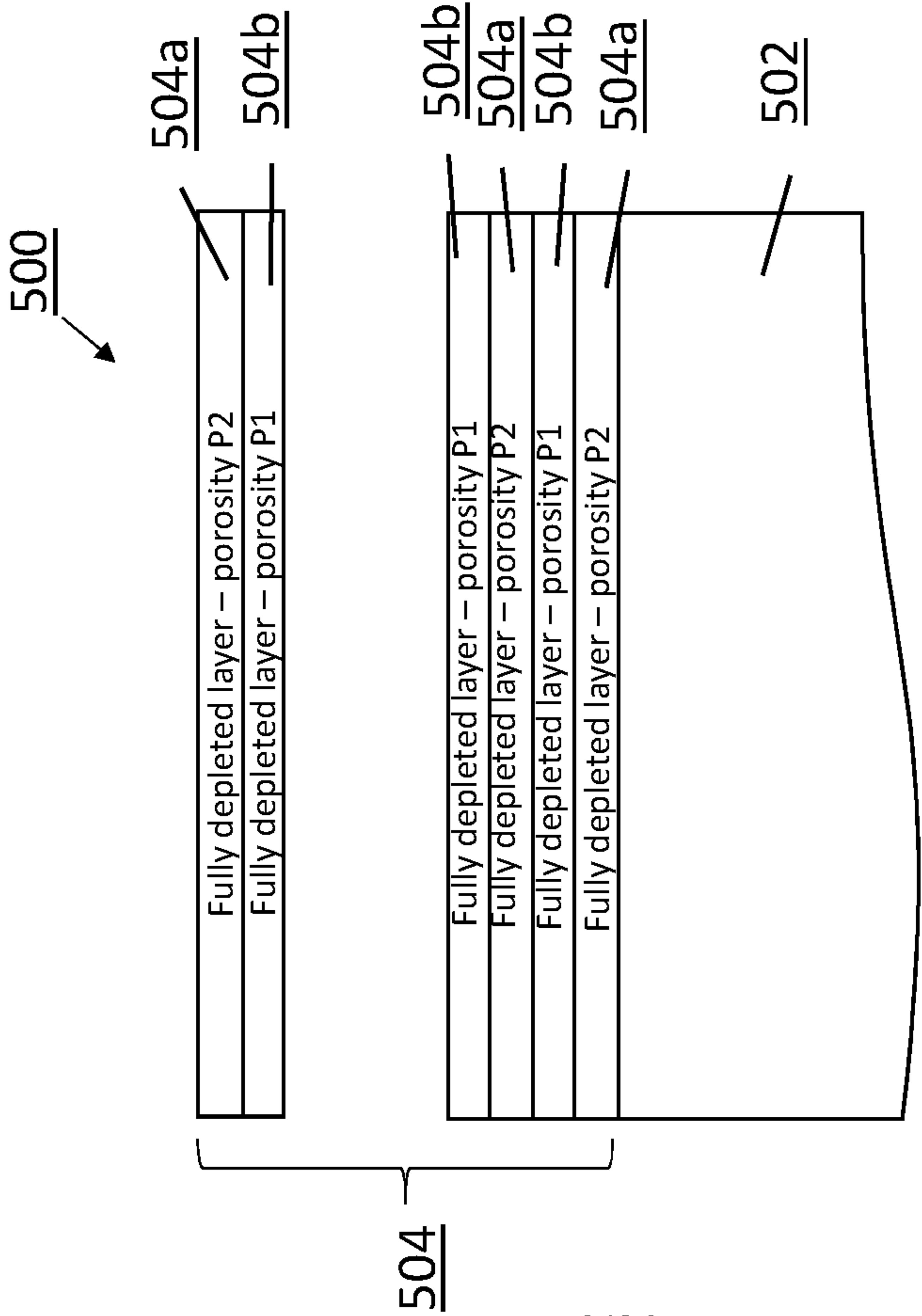


FIG. 14

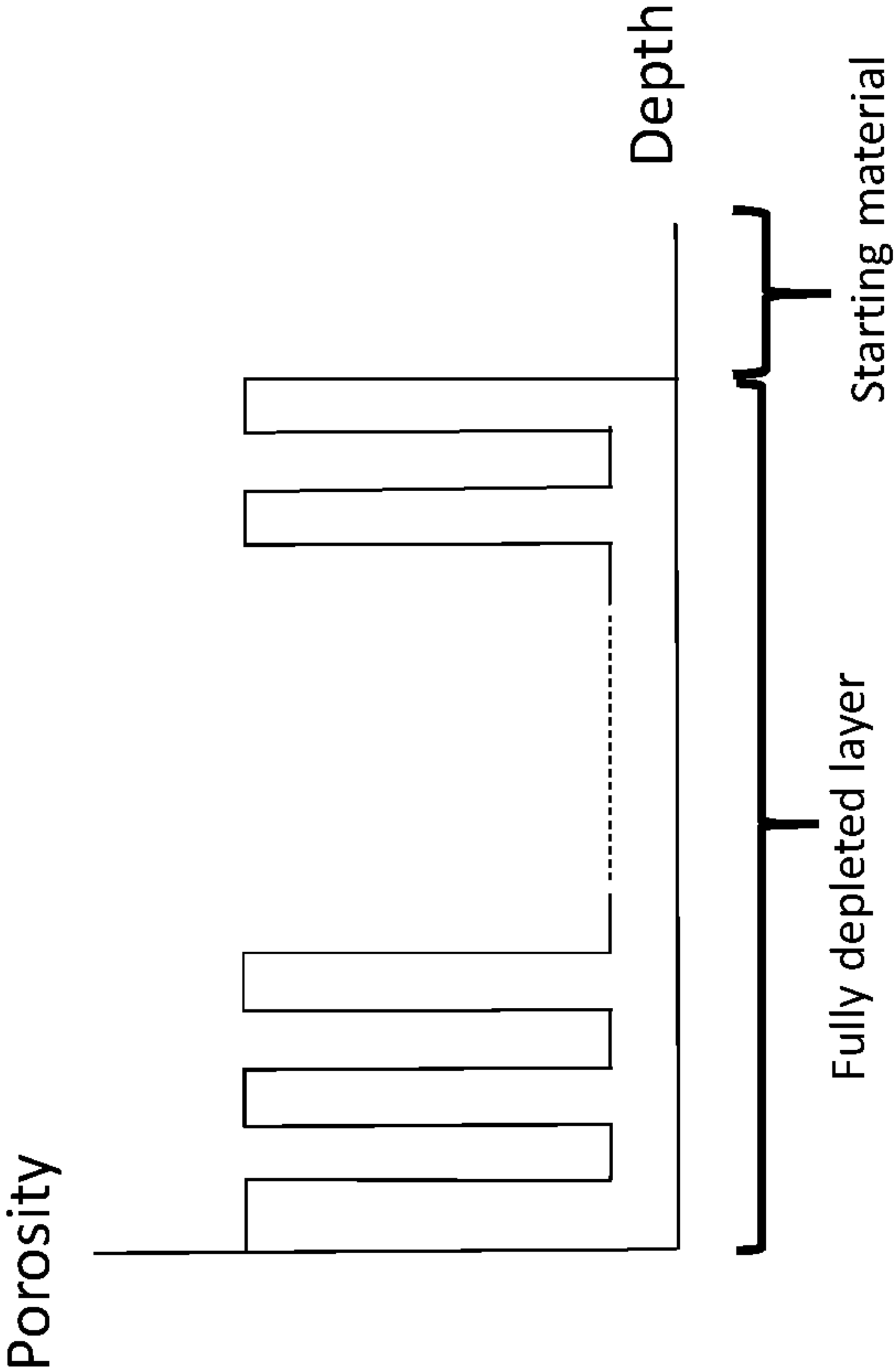


FIG. 15

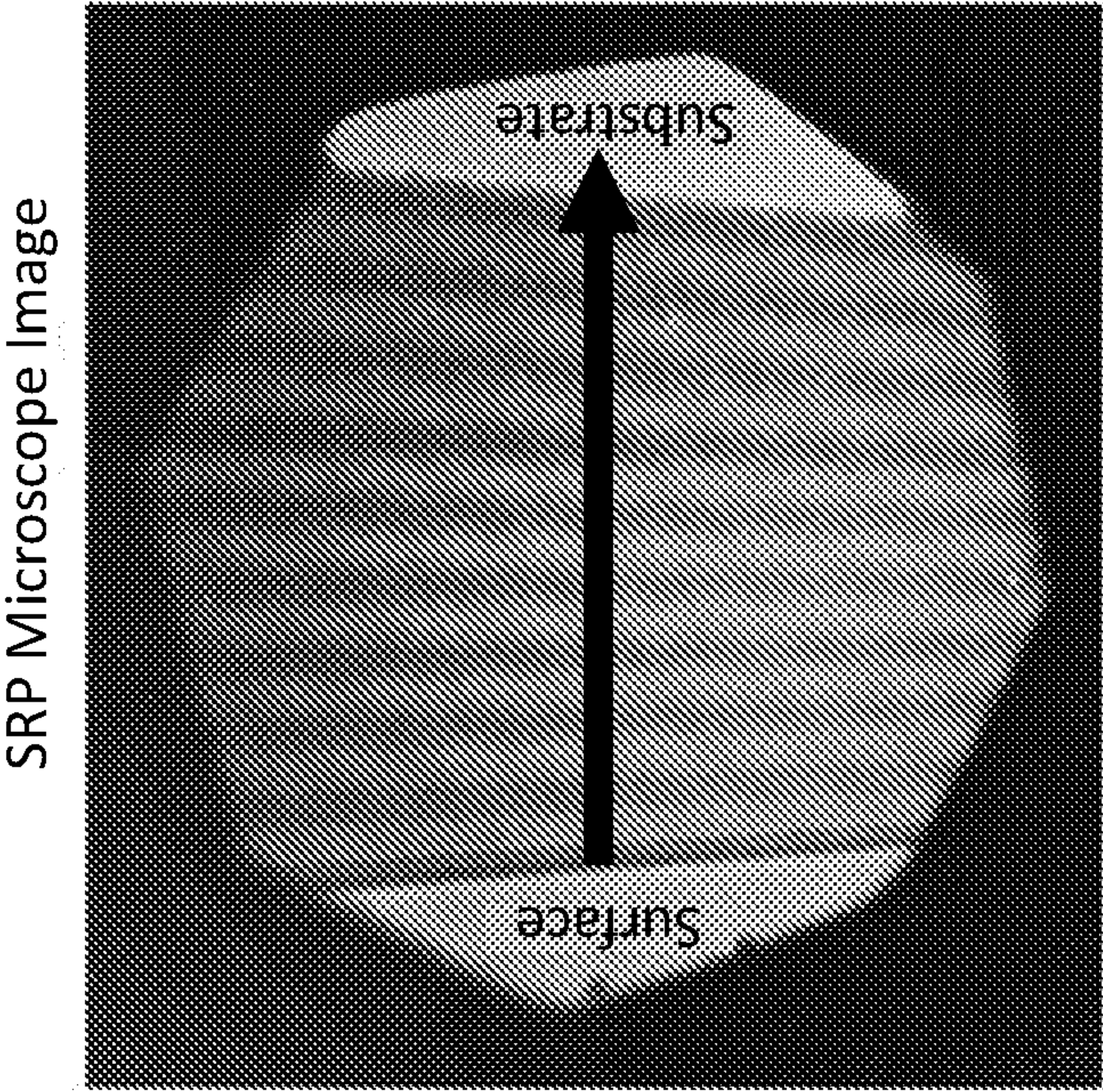


FIG. 16

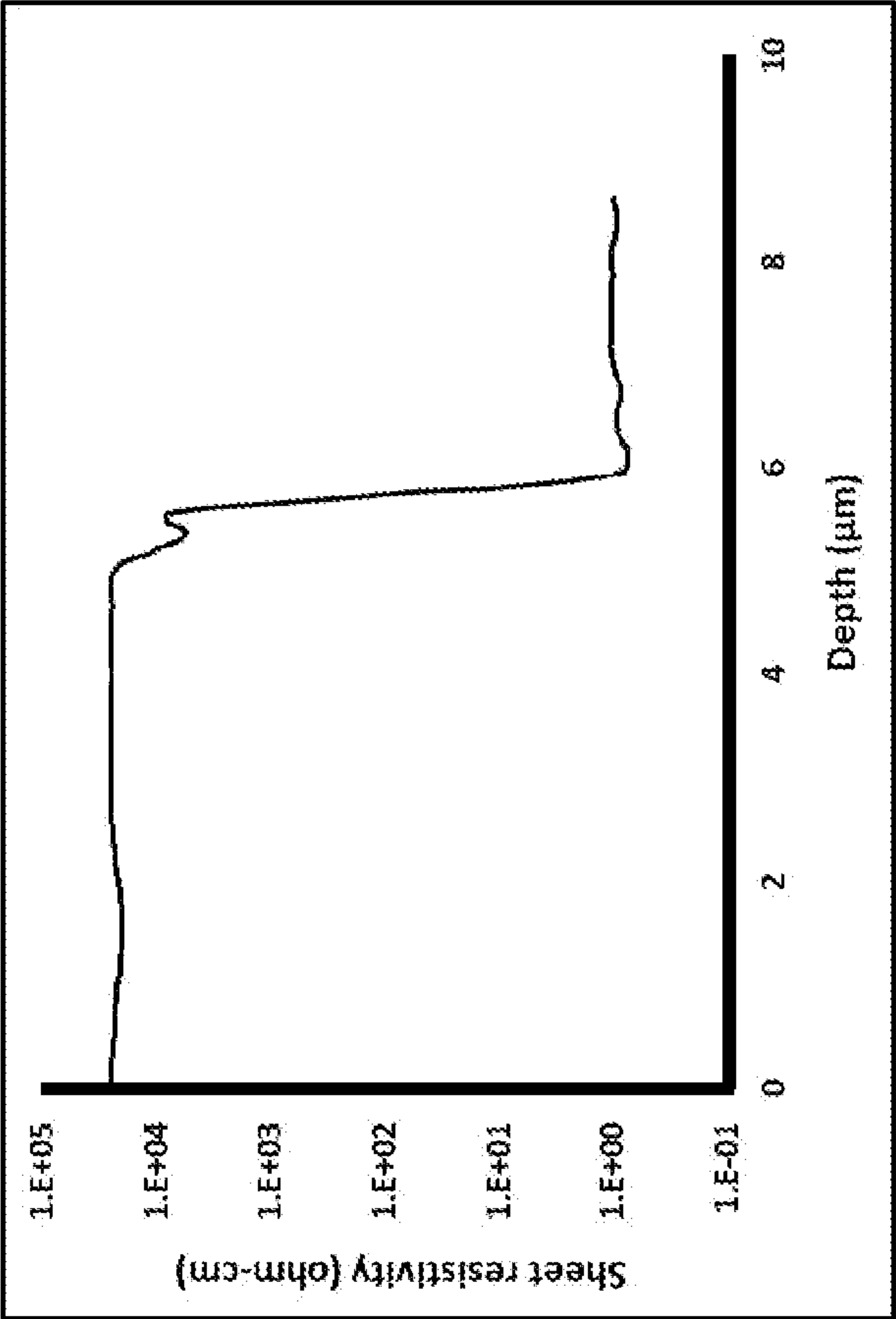


FIG. 17

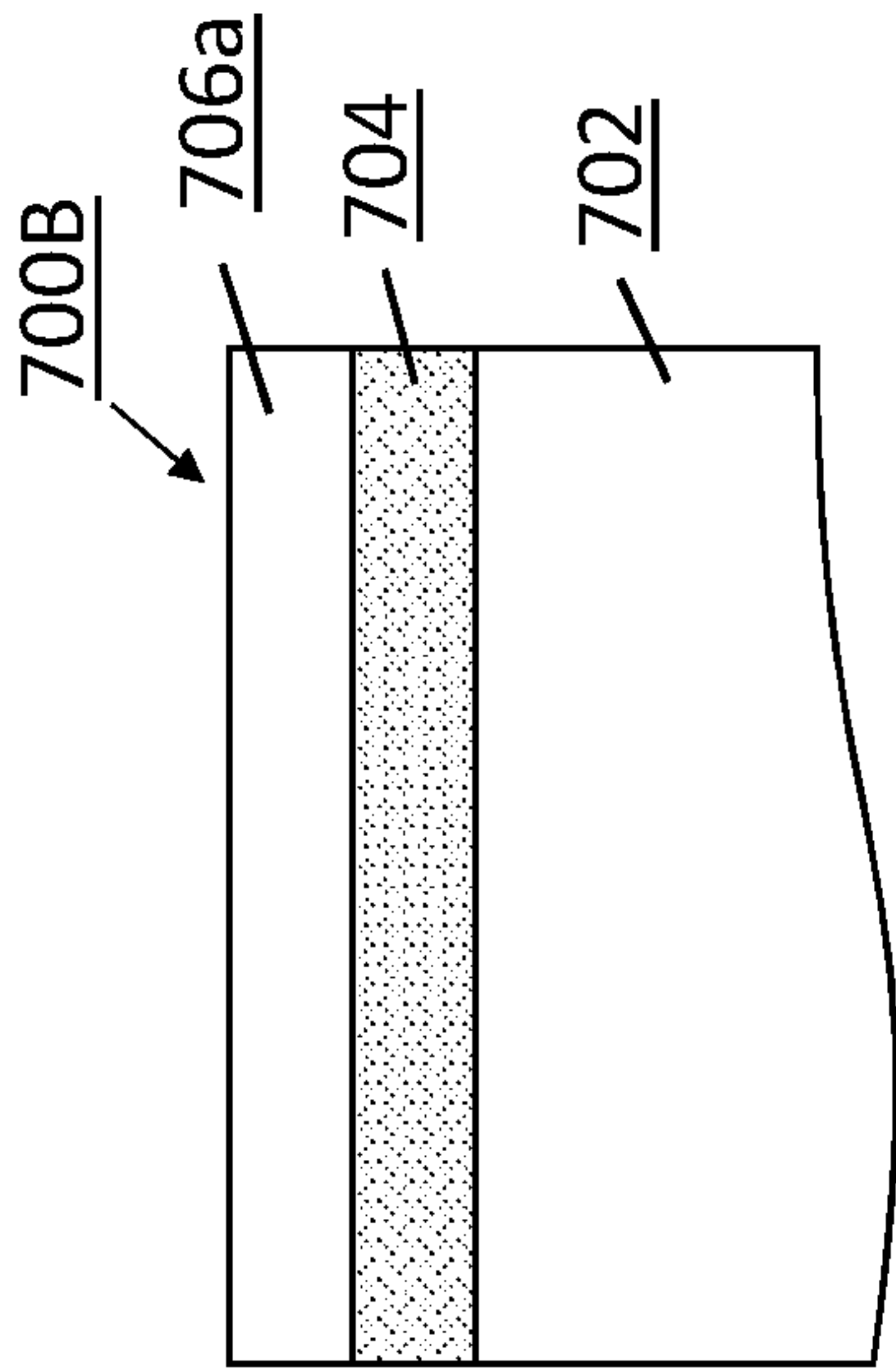


FIG. 19

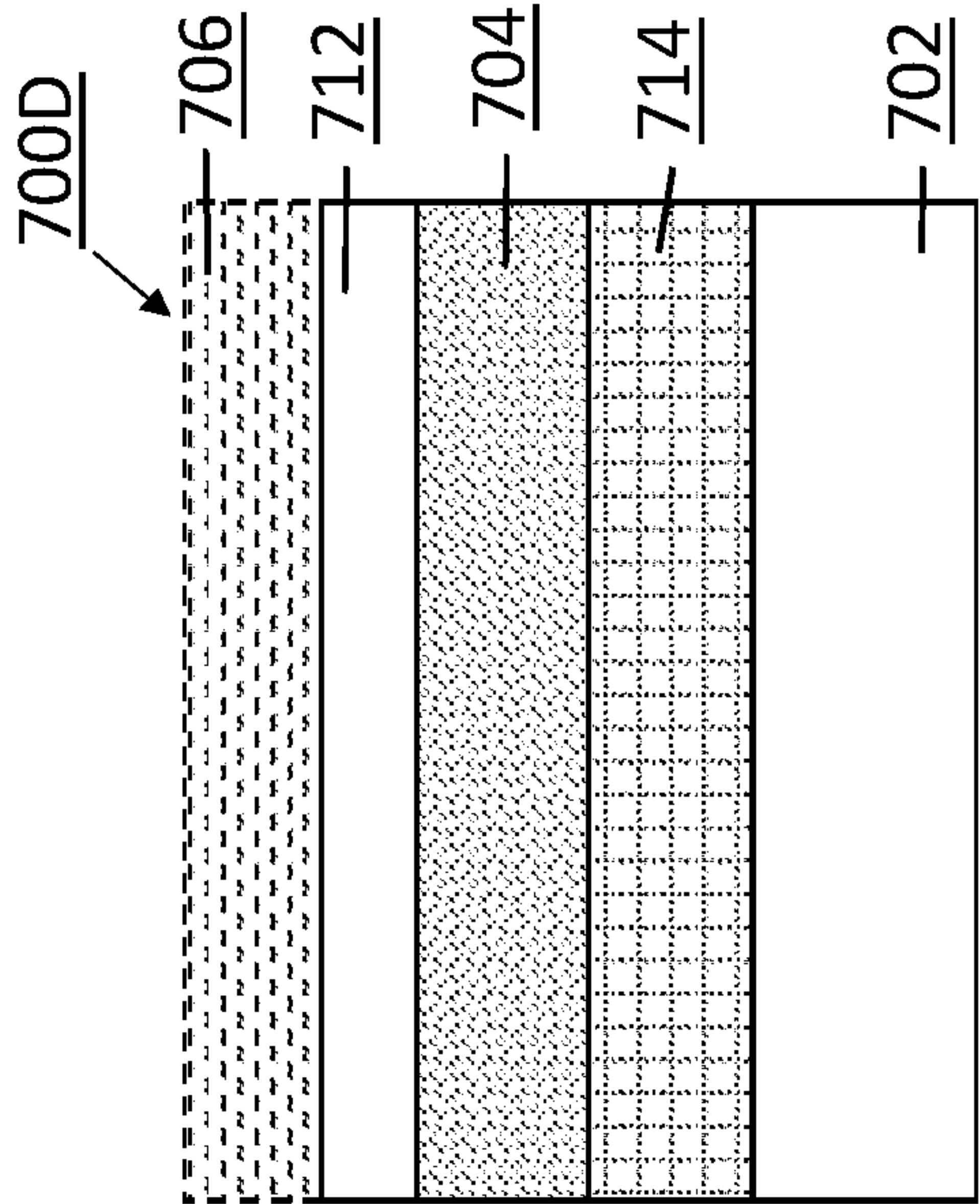


FIG. 21

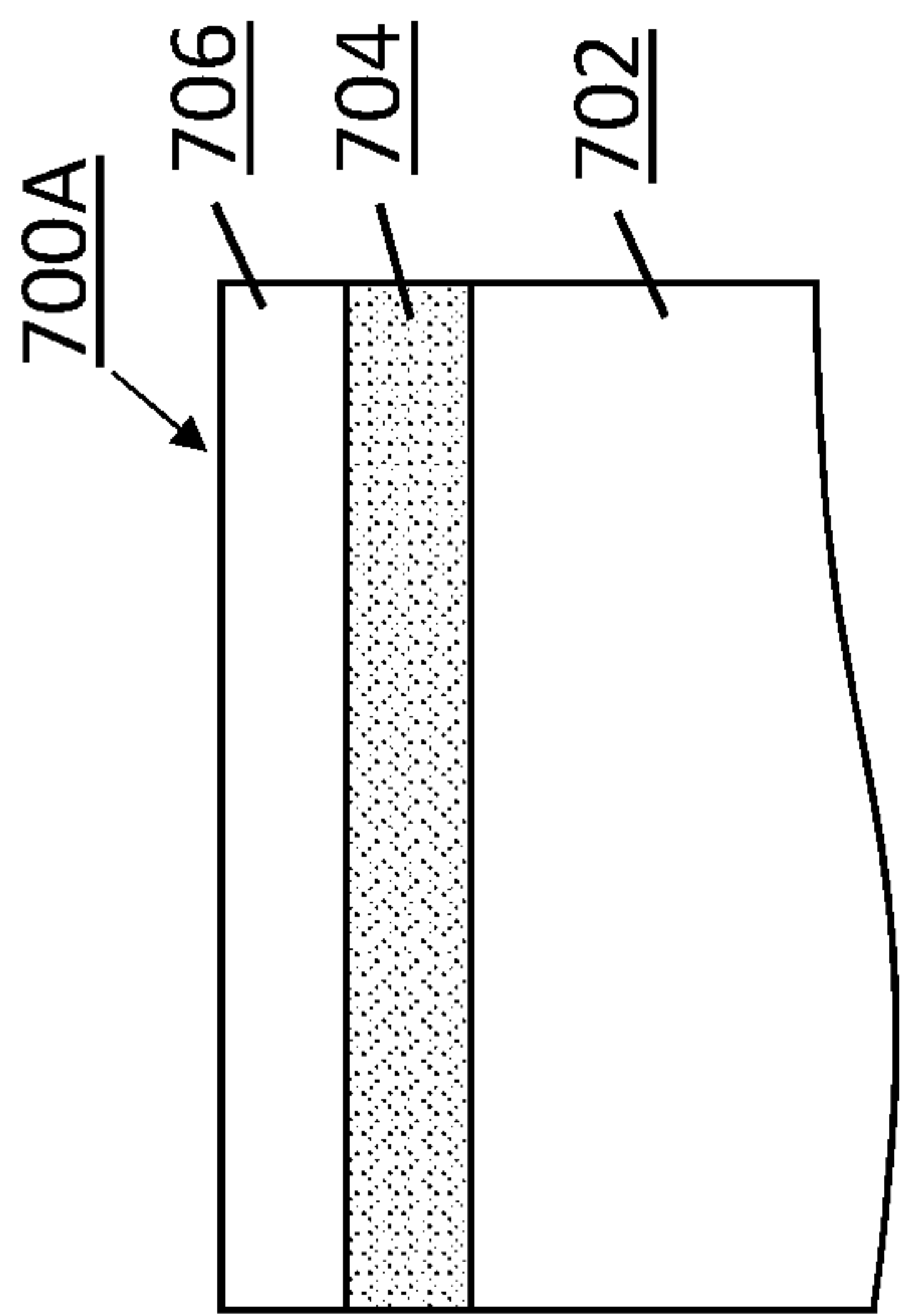


FIG. 18

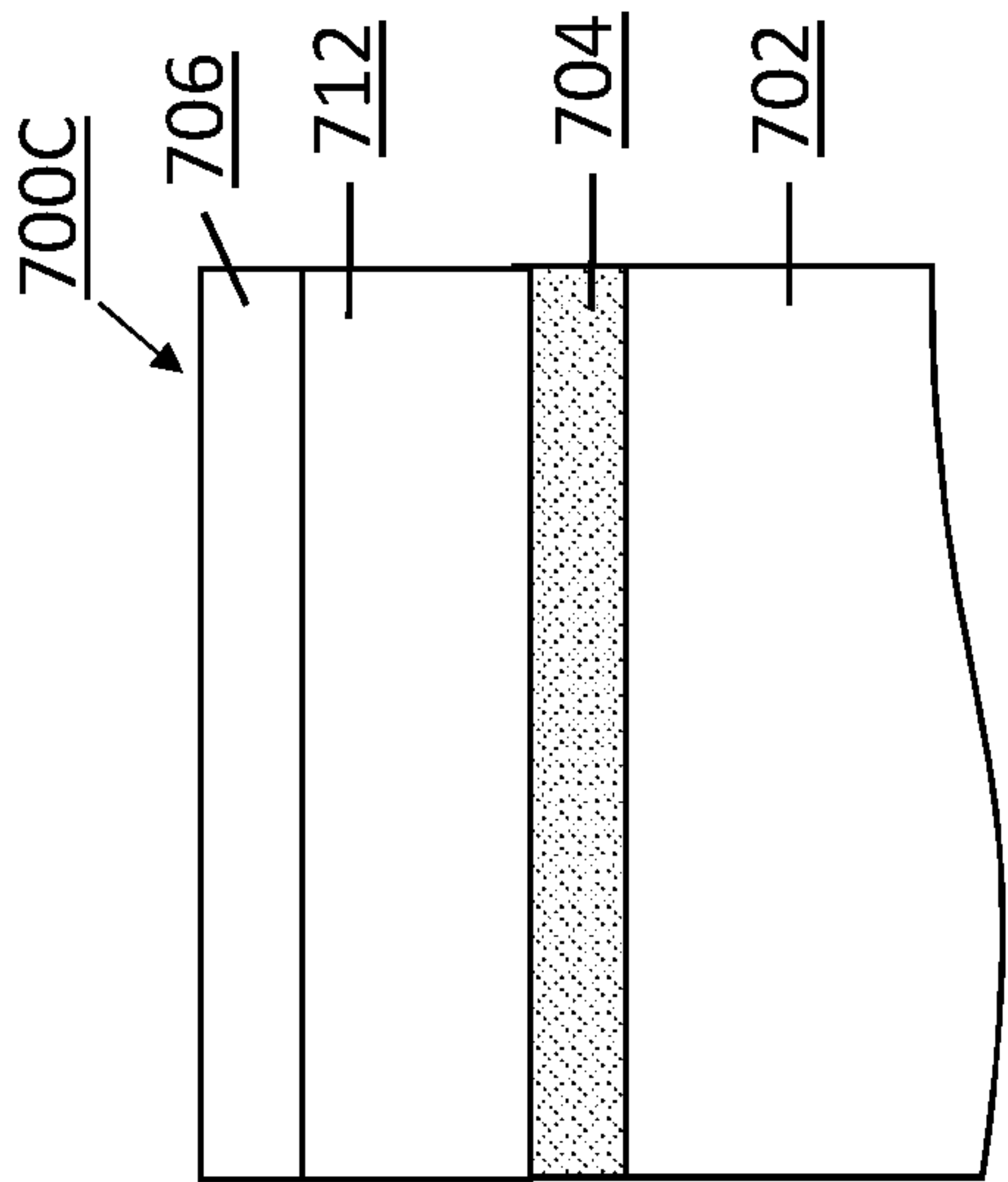


FIG. 20

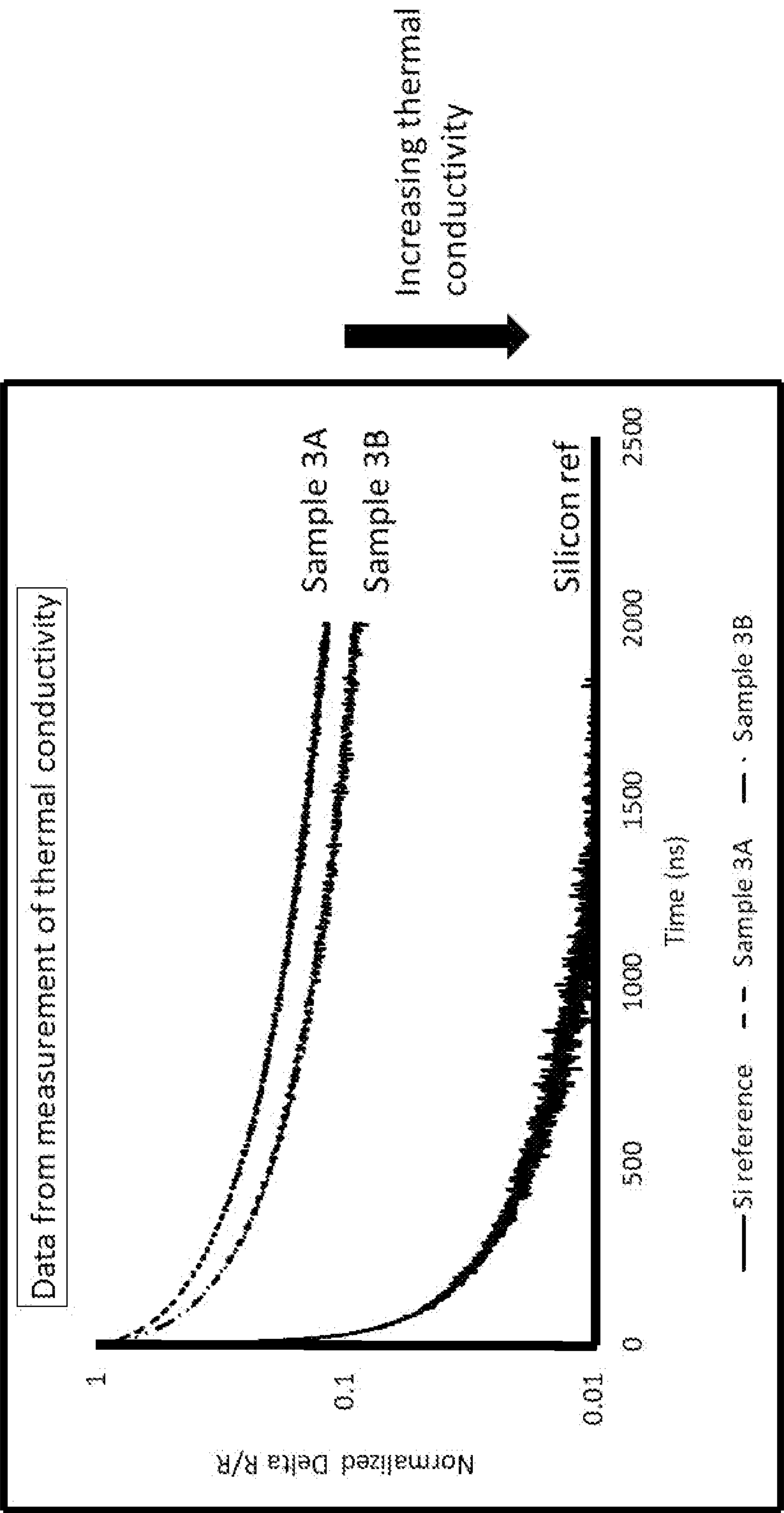


FIG. 22

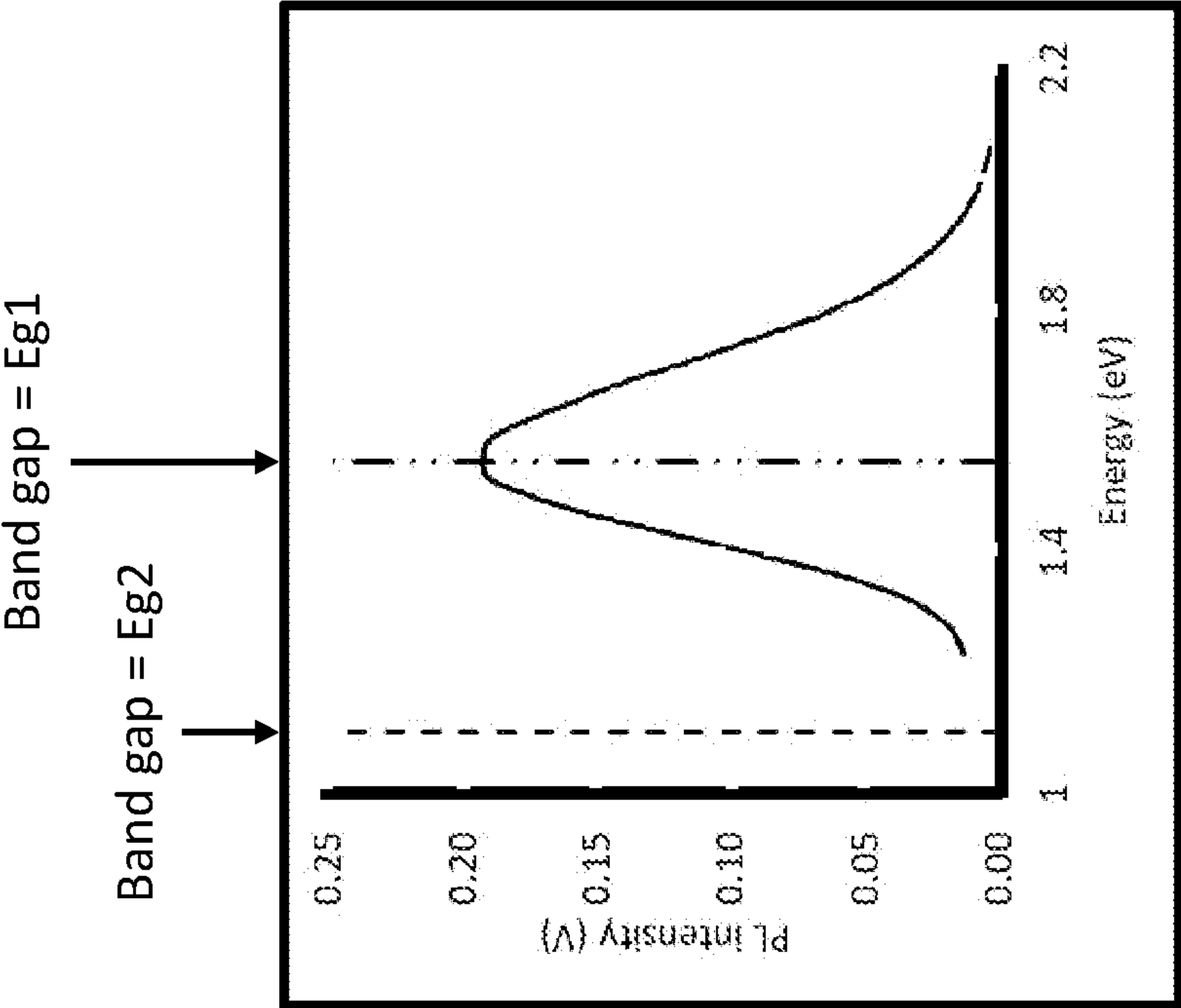


FIG. 23

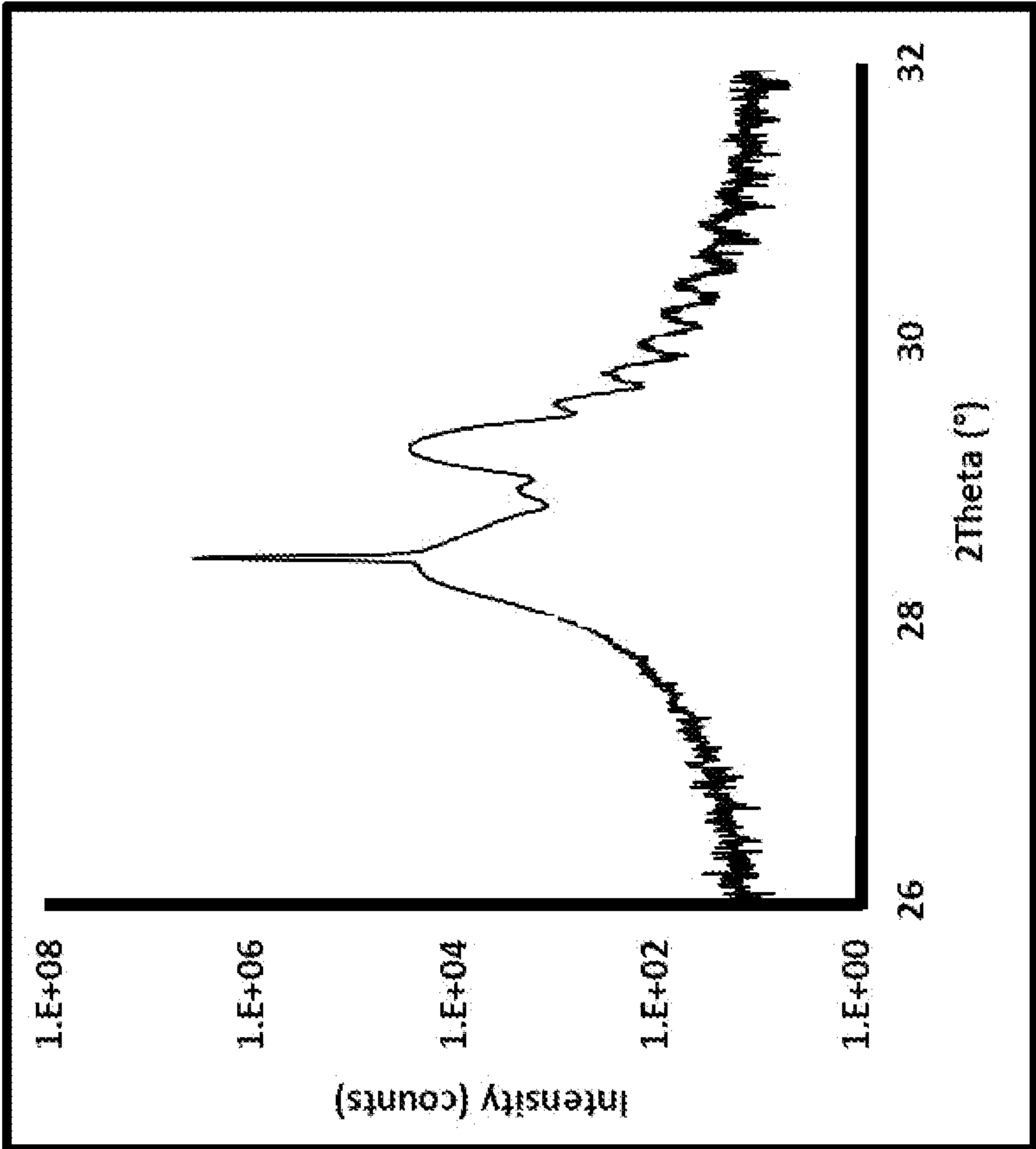


FIG. 25

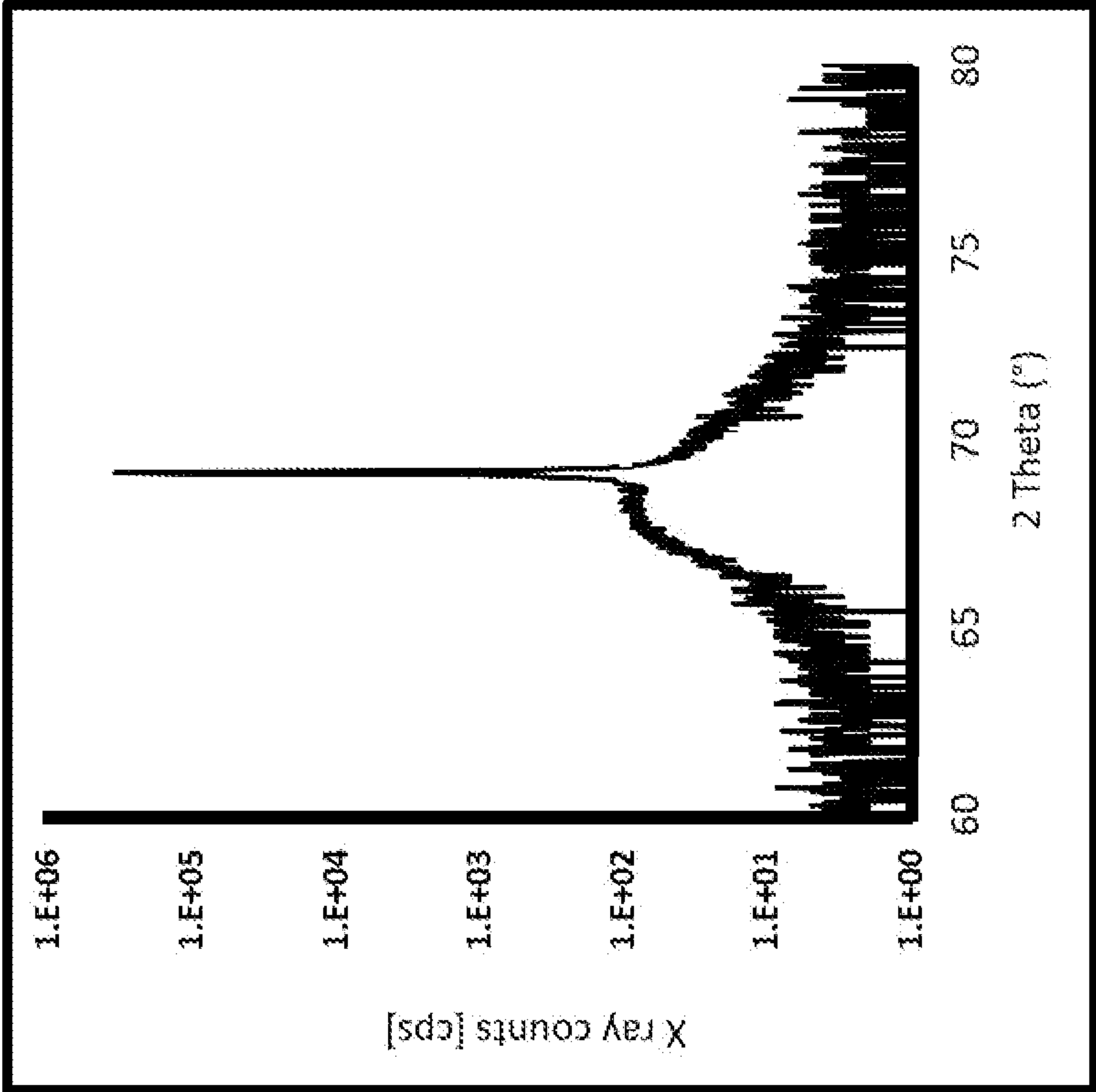
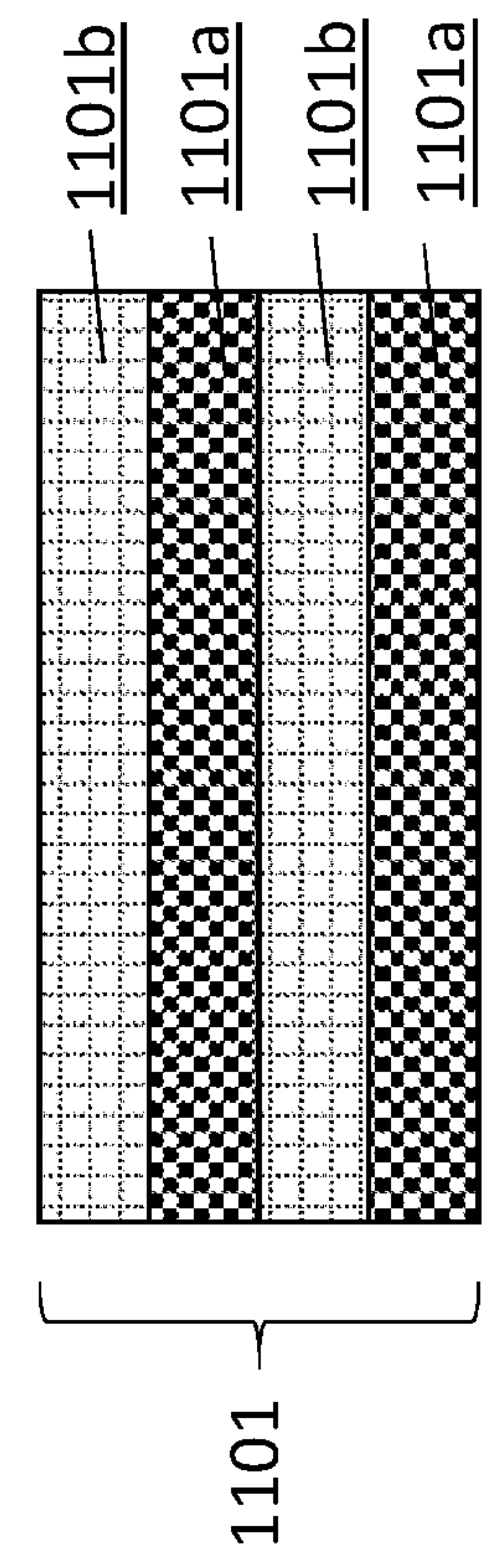
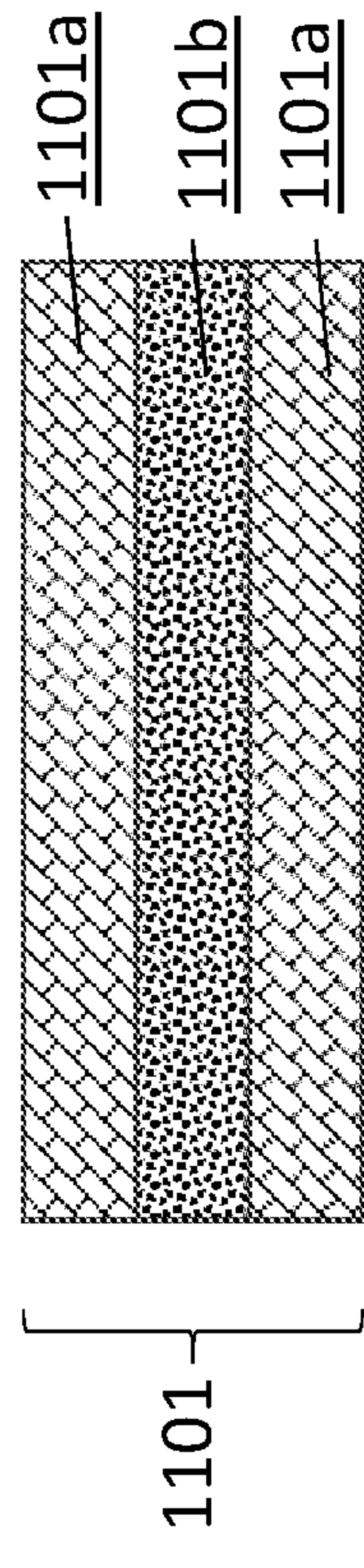


FIG. 24



Hi-Lo periodic structure

FIG. 27



Buried Hi porous region
for wafer separation

FIG. 28

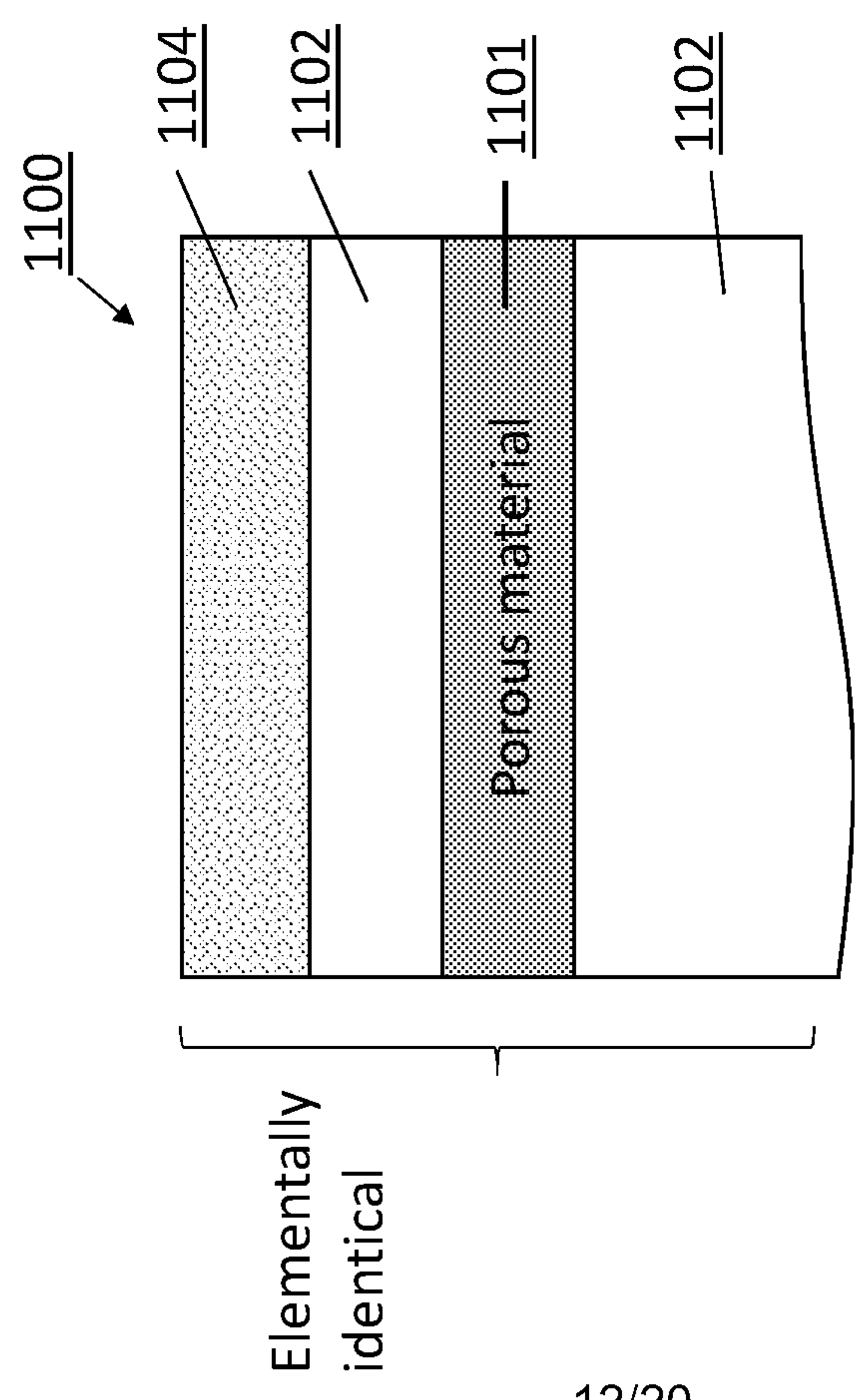


FIG. 26

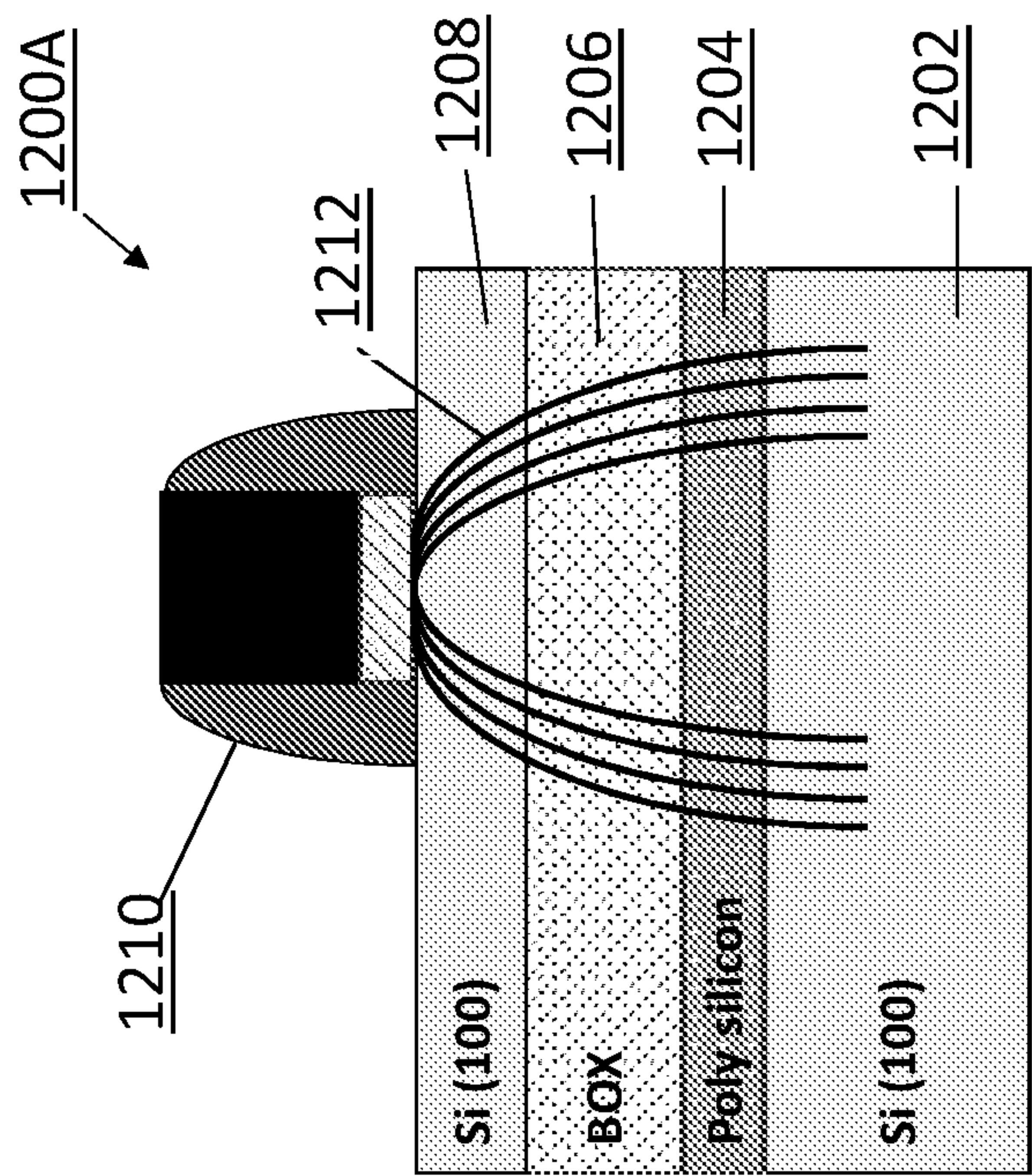


FIG. 29

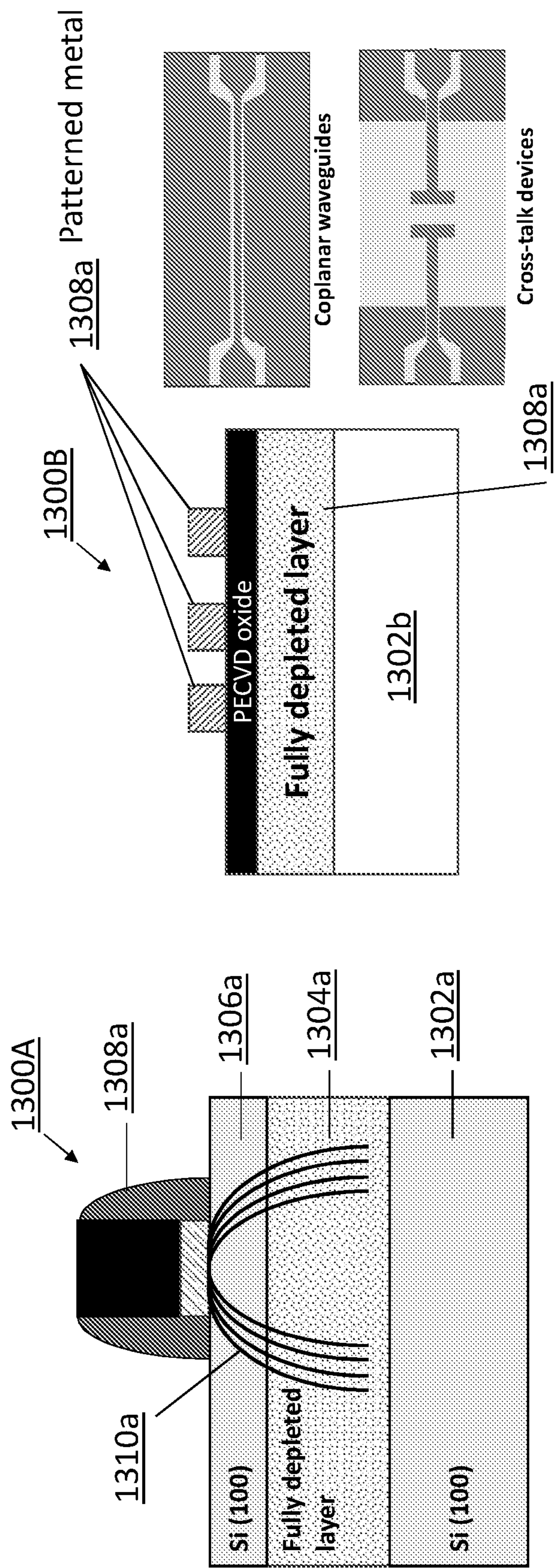


FIG. 31

FIG. 30

■ Process 2A ◆ Process 3A, 3B ▲ Process 4A

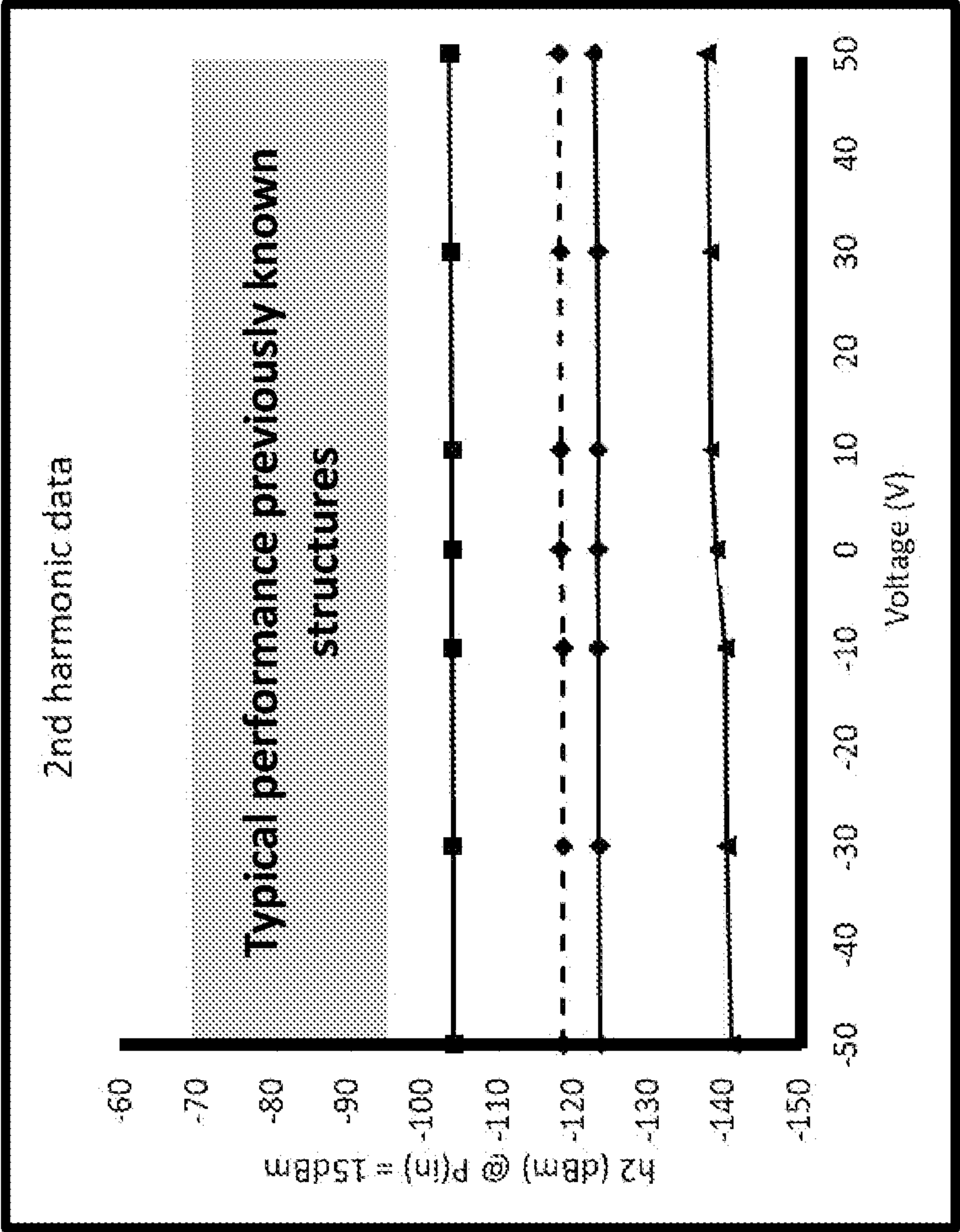


FIG. 32

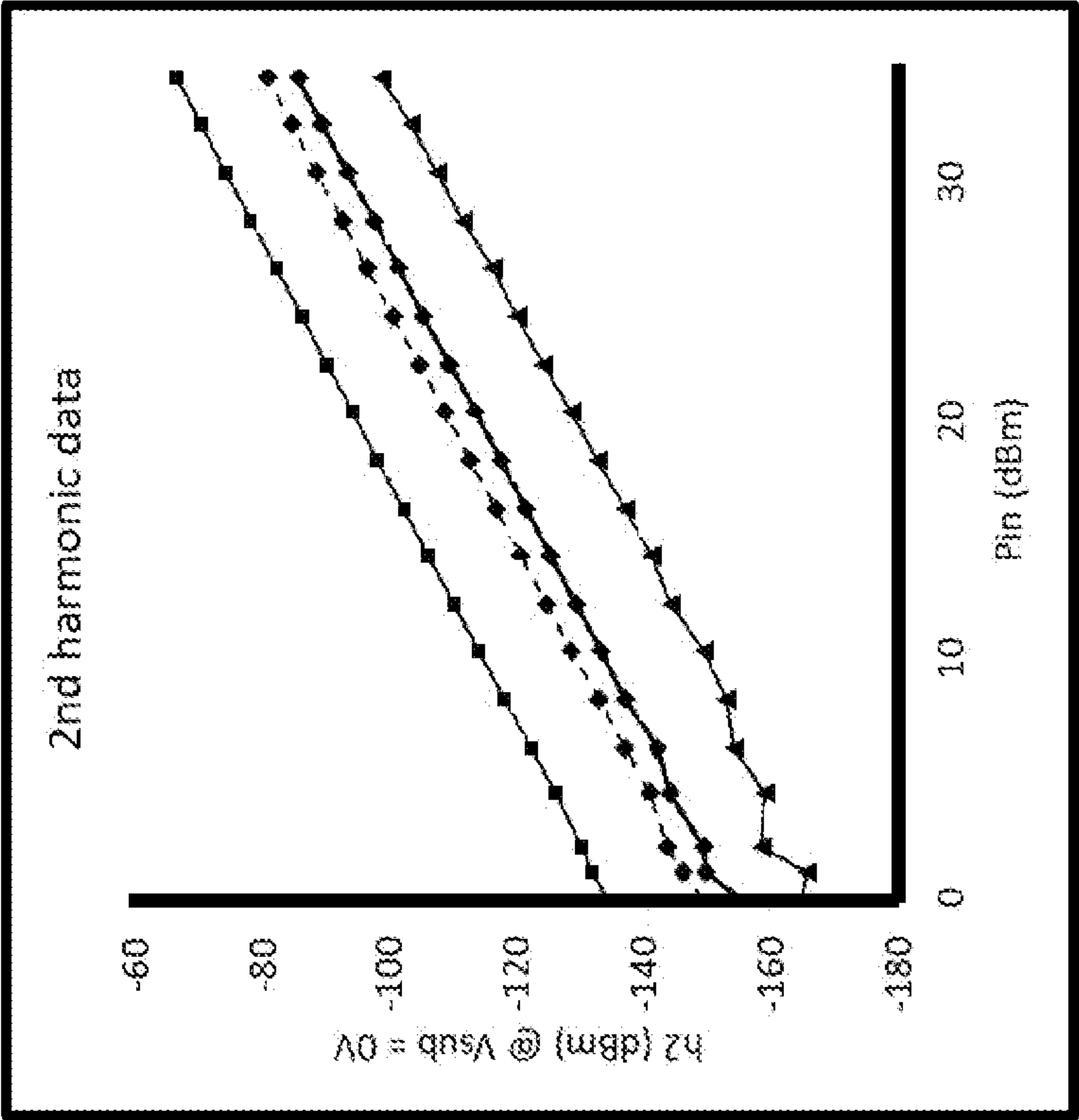


FIG. 33

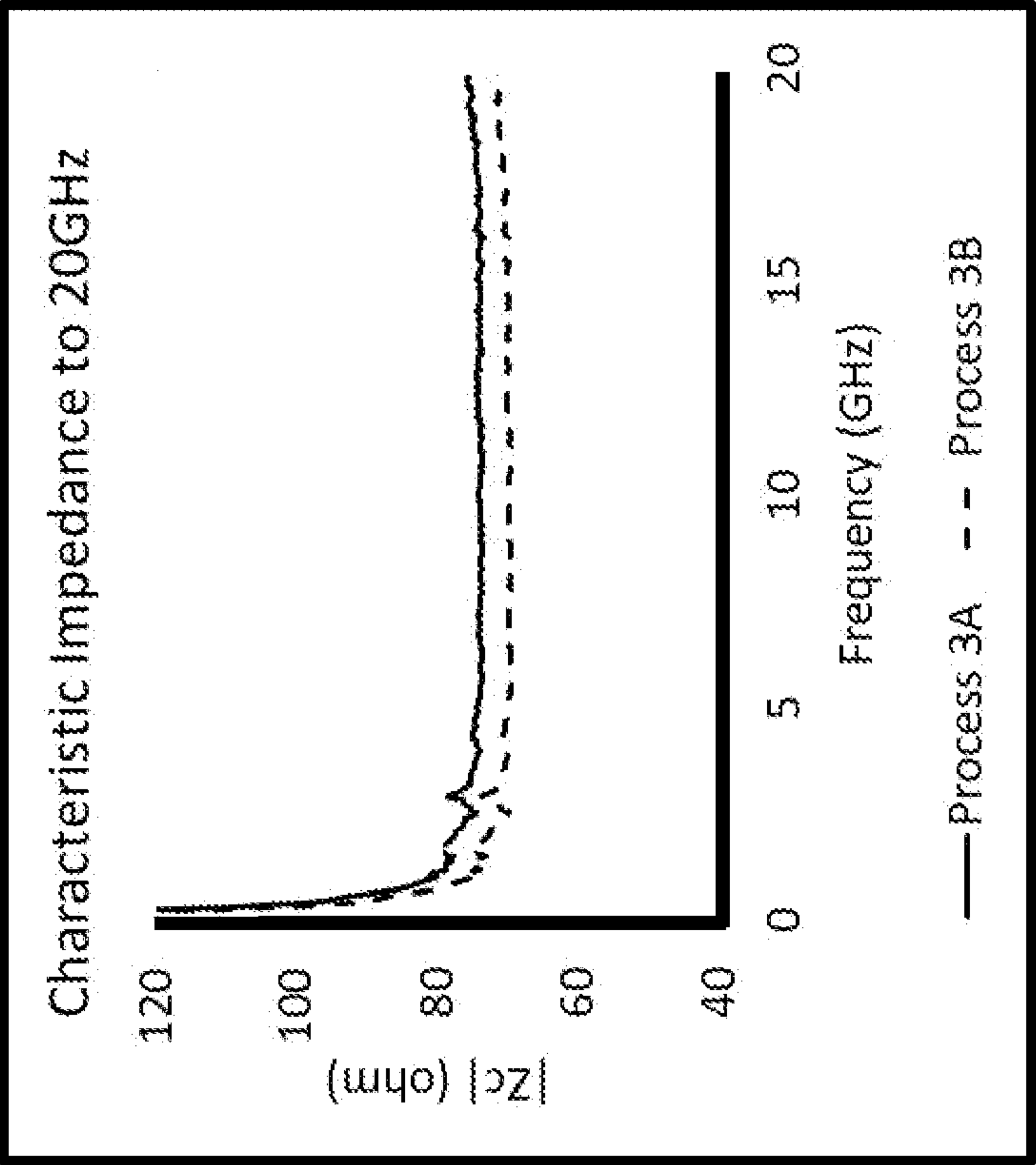


FIG. 34

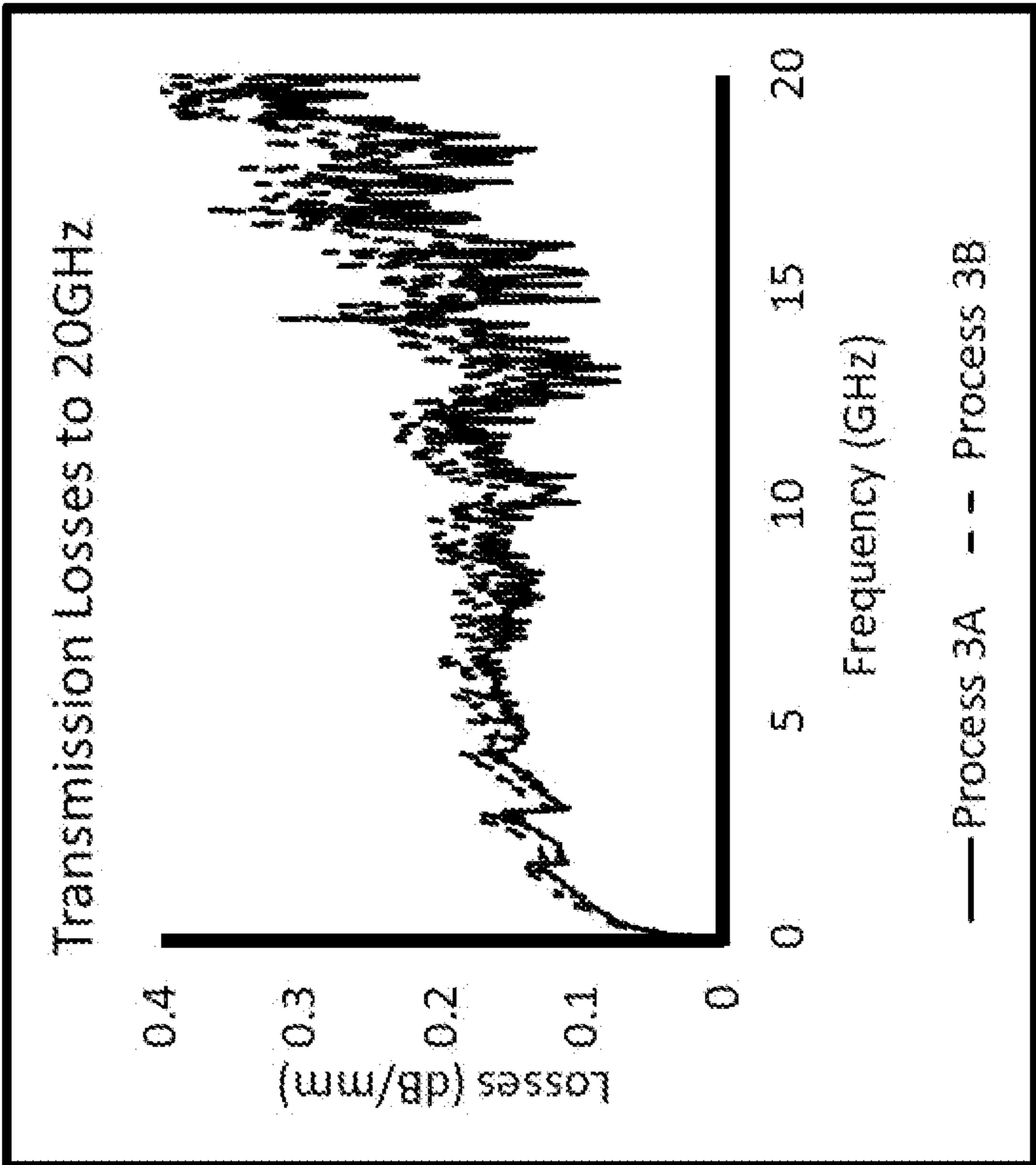


FIG. 35

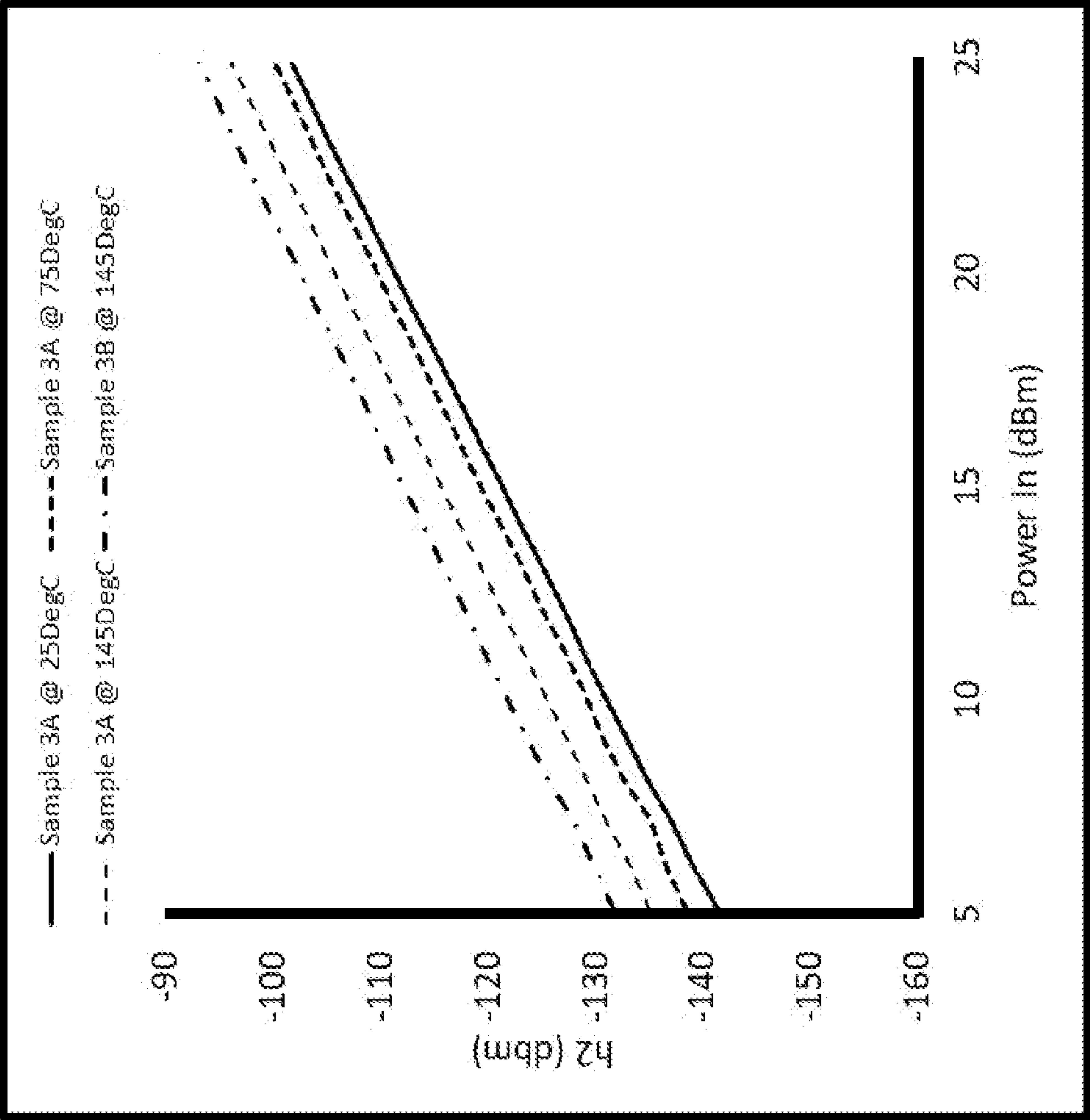


FIG. 36

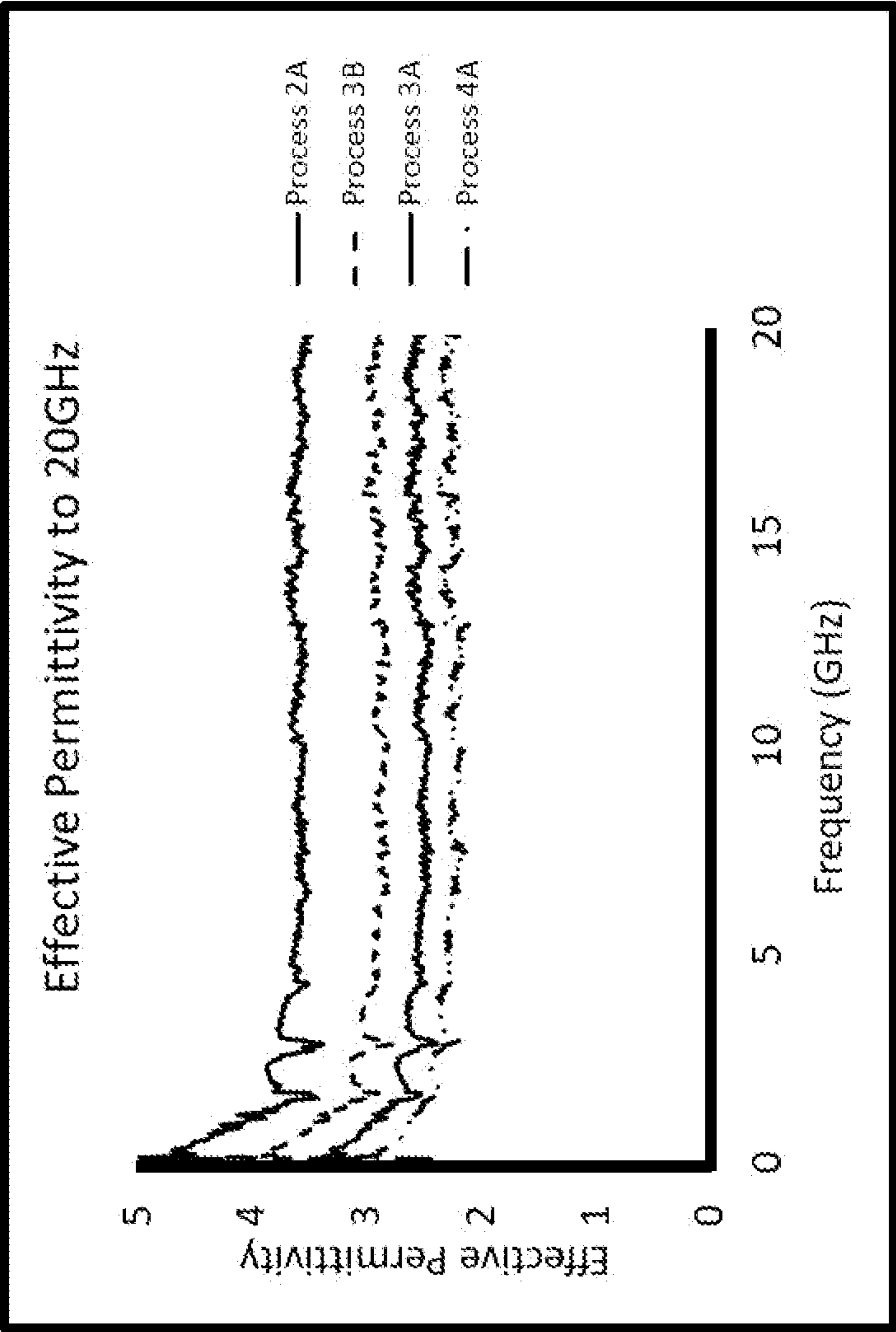


FIG. 37

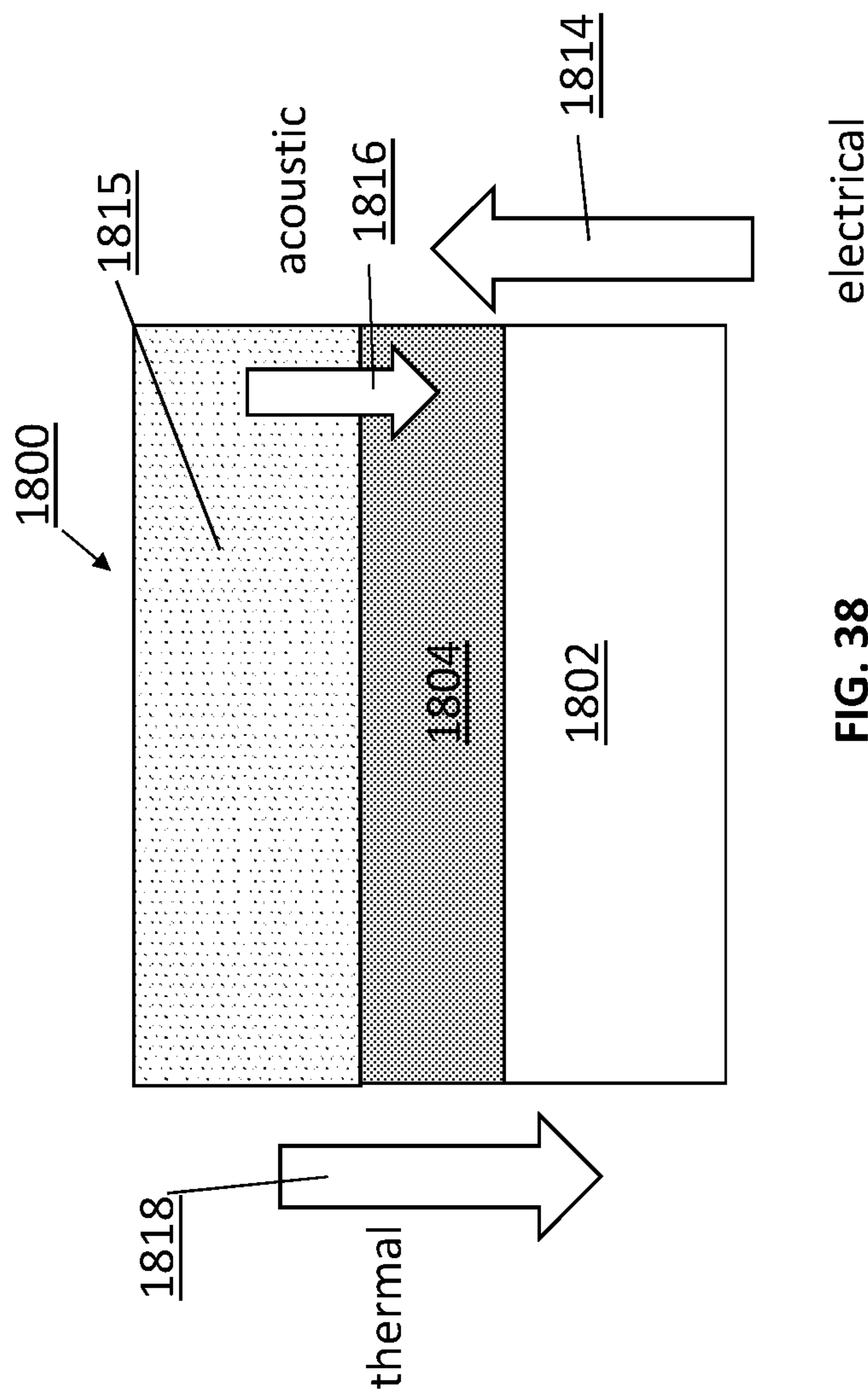


FIG. 38

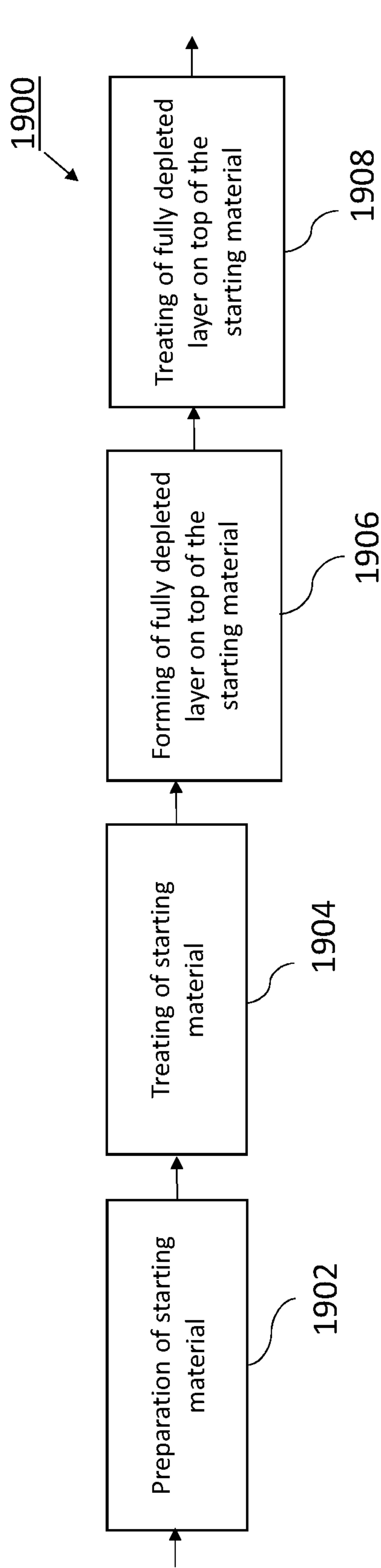


FIG. 39

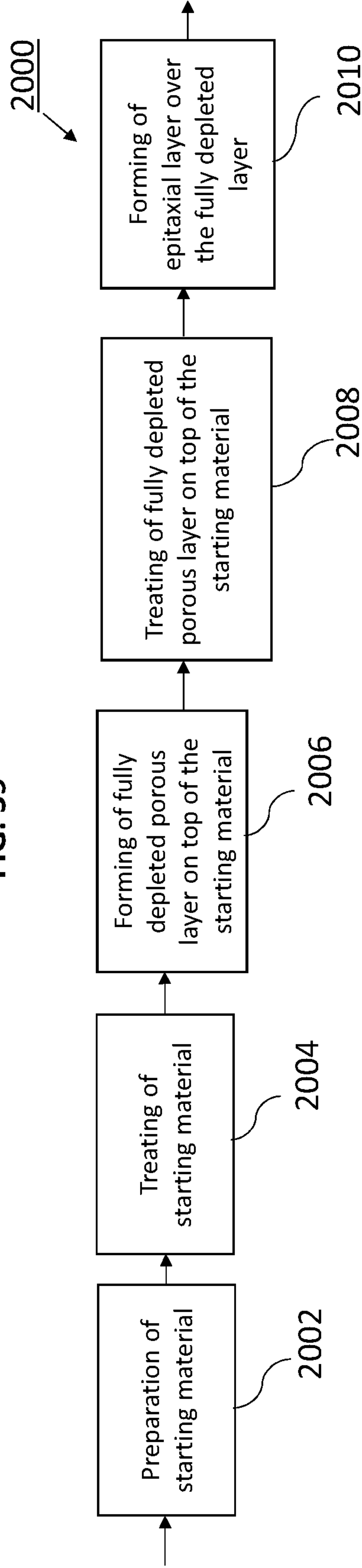


FIG. 40